NEXCOM

2026
Intelligent Platform & Service in Smart City
Product Selection Guide

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Creating Smarter Business

About NEXCOM
Intelligent Platform & Service in Smart City

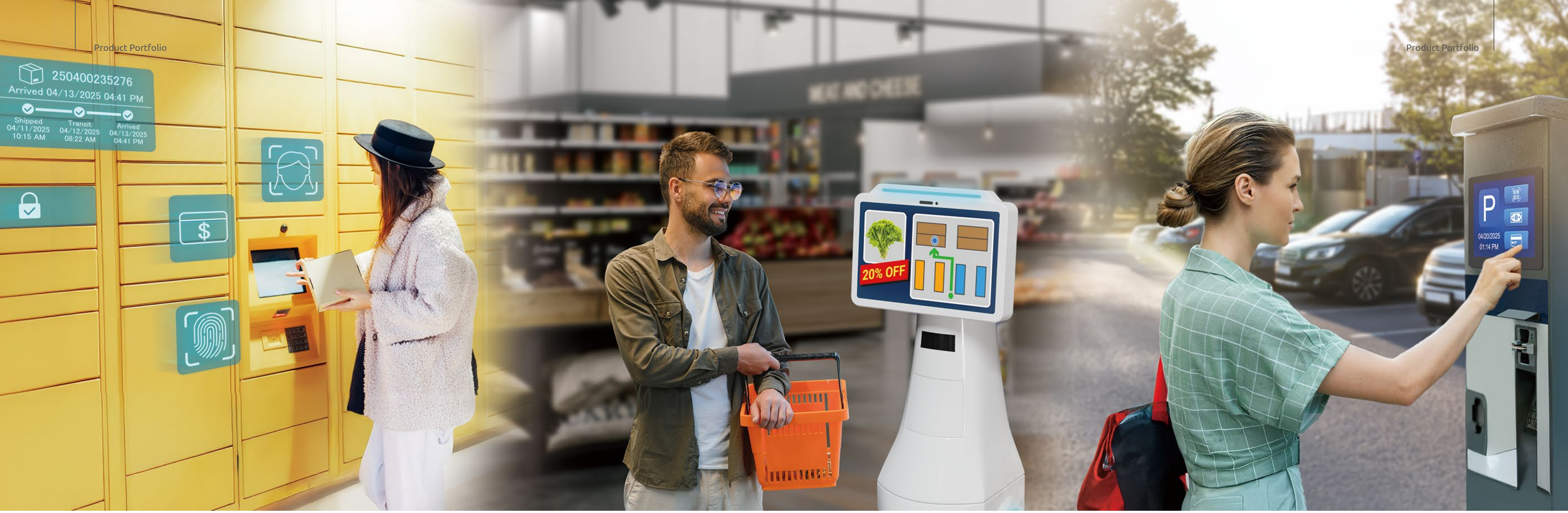
Founded in 1992, NEXCOM is committed to being your trustworthy partner in building the intelligent business. NEXCOM makes the difference by utilizing its industrial computing experience, a highly talented R&D team, strong world-class ODM services, and rapid support to customers. NEXCOM has worldwide customers from more than 50 countries, and we never stop growth with our business partners. As we accelerate towards the future, NEXCOM has been playing an important role in bringing intelligence & service in city.

NEXCOM's Intelligent Platform & Service(IPS) has extended and developed many products for use in AI, 5G, and smart city related applications. We're creating a safer working environment and saving operational costs through improvements in logistics for more efficient management. Through the application and development of 5G, a better internet experience can be realized. We support our business partners to further promote edge AI computing for IOT gateway, smart retail, packing surveillance system, smart vending machine…etc.

We focus on developing practical technologies, and constant growth brings us many advantages in the smart city sphere:

- Superior power designed for uninterrupted operations
- Smart and effective designs, resistant to extreme environments
- Various communication module options (LTE, 5G & Wi-Fi)
- Reserve expansion space for extend functionality
- Elegant appearance design integrated into smart city without any sense of inconsistency.

NEXCOM has the passion, hope and dedication to keep moving forward making daily lives better through innovation. NEXCOM is forging ahead into the future and making it a success with our business partners!



Indoor Product Series

—

Neu-X Series

Edge Computing System

- Fanless & Compact Design
- Just-fit I/O
- Power Adaptor Included
- Scalable with 5G/LTE, Wi-Fi & BT

AIEdge-X Series

Edge AI Computing System

- Designed for Edge AI Applications
- Optional NVIDIA® GPU card, NVIDIA® Jetson Orin™ and Hailo Module Add-ons
- Scalable with 5G/LTE, Wi-Fi & BT

SPPC/XPPC/ XPPD Series

Embedded Touch Computer/Display

- Slim & Fanless Design
- Anti-fingerprint Coating
- Easy Clean-flat Screen & IP65 in Front
- Multi-PCAP Touch
- Scalable with 5G/LTE, Wi-Fi & BT

Semi-Outdoor Product Series

—

HPPC/HPPD Series

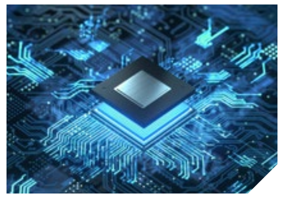
High Brightness Embedded Touch Computer/Display

- Sunlight Readable
- AF+AG Coating
- Auto Dimming
- Solar Resistance
- Scalable with 5G/LTE, Wi-Fi & BT

NDiS Series

Duro Edge Computer

- Fanless & Compact Design
- Wide Temperature: -20 °C to 60°C
- Wide Input Voltage: +12V to 24V DC
- Scalable with 5G/LTE, Wi-Fi & BT



X series

Embedded Computing Board

- Standard 3.5" & Mini-ITX Form Factor
- Rich I/O Design
- Wide Temperature: -40°C to 85 °C
- Scalable with 5G/LTE, Wi-Fi & BT

Core Competencies

Committed to Customer Success
Help You Succeed in Your Business Endeavors

Premium Computing Design Capability

Computing power applications, which is why NEXCOM offers a wide range of computing platform to meet different needs.

- Intel Atom® platform: Apollo Lake, Elkhart Lake, Alder Lake-N, Amston Lake & Twin Lake
- Intel® Core™ i platform: Coving Core i –S/H/U & Core Ultra AI PC
- NVIDIA® Jetson Orin™ NX/Orin Nano™ integrated
- AMD Ryzen™ platform

Reliability Quality

- Fanless design: Resistant to extreme environmental conditions
- Product approval: Rigorous internal verification process
- Certification: Compliant with worldwide EMC/EMI and Safety certification by request.
- Digital and Green Manufacturing: Compliant with ISO 14067

Wireless Communication Expansion

For the diverse range of wireless applications, NEXCOM specializes in RF communication expansion. We offer a comprehensive series of proprietary Mini PCIe/M.2 modules that provide users with maximum flexibility in optimizing wireless connectivity configurations.

- 4G LTE, 5G
- Wi-Fi 6/6E
- Wi-Fi 7

AI Technology

- NVIDIA® (GeForce/Quadro, Jetson Orin™)
- Intel x OpenVINO™
- AMD x ROCm™
- Hailo AI accelerator module (M.2 & Mini PCIe)
- Co-work with partners in driving deeper customer engagement in AI + edge computing applications.
- Provide edge processing and AI capabilities to software partners/developers for innovation and the creation of new business models.

OEM/ODM Services

- Over 30 years of experience in industrial-grade computer design and manufacturing
- Proven design capabilities in customized system and software integration
- Customization service on BIOS, mainboard and system design
- Certificated, 100%-owned manufacturing facilities in Taiwan
- Expertise in industrial PC solution with vertical domain know-how
- Accommodates small to medium quantities with fast time-to-market delivery

Software Service

- Customized BIOS
- Secure system development (TPM, Secure Boot)

Edge AI Solution

NDiS B363

Duro Edge Computer Powered by Intel® Core™ Ultra Processor (up to 22.5 TOPS)

- Support 2 independent 4K@60Hz display outputs
- 4 x USB 3.2
- 2 x RS-232/422/485
- 1 x 1GbE LAN, 1 x 2.5G GbE LAN
- 3 x M.2 Key B/E/M
- DC 12V~24V power input
- Operating temperature: -20°C~60°C

AIEdge-X®80

Edge AI Computer NVIDIA Jetson Orin™ NX/Orin Nano™ (up to 157 TOPS)

- NVIDIA Jetson Orin™ NX 16GB/8GB (157/117 TOPS)
- NVIDIA Jetson Orin Nano™ 8GB/4GB (67/34 TOPS)
- 4 x Intel® 1GbE LAN port, 1 x HDMI®, 2 x COM port, 4 x USB, 1 x USB OTG
- 1 x M.2 Key B 3042/3052 for 5G/LTE, 1 x M.2 Key M 2280 for storage
- Extended operating temperature -20°C~60°C
- DC 24V power input with 3-pin Phoenix terminal block

AIEdge-X®310

Industrial AI Computing System at The Edge Powered by 14th/13th/12th Gen Intel® Core™ i Processor and NVIDIA® Graphics Card

- 1 x PCIe x16 slot, supports graphics card up to 650W
- 2 x M.2 Key M
- Support 2 x 2.5" SATA HDD/SSD
- AC 100V~240V power input
- Operating temperature: 0°C~45°C

AIEdge-X®510

Industrial AI Computing System at The Edge Powered by Intel® Xeon Granite Rapids-W Processor

- 5 x PCI-e 5.0 x16 slot, 2 x PCI-e 5.0 x4 slot
- 4 x USB 2.0, 6 x USB 3.2, 4 x RS-232, 2 x RS-232/422/485
- 3 x M.2 Key B/E/M expansion slot
- 8 x 2.5" SSD or 4 x 3.5" HDD
- AC 100V~240V power input
- Operating temperature: 0°C~45°C

X202

3.5" Embedded Computing Board Powered by Intel® 13th Gen Core™ i Processor

- 2 x DDR5 SO-DIMM, non-ECC, unbuffered, up to 96GB
- 2 x HDMI® 1.4, up to 4096x2160@30Hz
- 1 x 2.5GbE RJ45 port, Intel® I226
- 1 x 1GbE RJ45 port, Intel® I219
- 1 x USB 3.2 Gen 1x1, Type-A
- 3 x USB 2.0
- DC +12V power input

2026 New Products

NDiS B562 w/ Dock∞

Duro Edge Computer Powered by Intel® Core™ Processor (Series 2)/Intel® Core™ i Processor

- Support PCIe 4.0 1x16/PCIe 4.0 2x8 expansion card/2 x 2.5" SSD swap bay
- 3 x USB 3.2 Gen 1x1, 2 x USB 2.0, 2 x DP 1.2
- 1 x 1GbE + 2 x 2.5GbE LAN, 2 x COM port (RS-232/422/485)
- 3 x M.2 Key B/E/M
- DC +12V~24V power input
- Operating temperature: -20°C~60°C

NDiS B562

Duro Edge Computer Powered by Intel® Core™ Processor (Series 2)/Intel® Core™ i Processor

- 1 x HDMI® 2.0 output, up to 4096x2160@60Hz
- 3 x USB 3.2 Gen 1x1, 2 x USB 2.0, 2 x DP 1.2
- 1 x 1GbE + 2 x 2.5GbE LAN, 2 x COM port (RS-232/422/485)
- 3 x M.2 Key B/E/M
- DC +12V~24V power input
- Operating temperature: -20°C~60°C

NDiS B361

Duro Edge Computer Powered by Intel® Core™ i Processor

- 2 x HDMI® 1.4 output, up to 4096x2160@60Hz
- 1 x USB 3.2, 3 x USB 2.0, 2 x COM port (RS-232/422/485)
- 1 x 1GbE LAN, 1 x 2.5GbE LAN
- 3 x M.2 Key B/E/M
- DC 12V~24V power input
- Operating temperature: -20°C~60°C

NDiS B340 w/ Dock∞

Duro Edge Computer Powered by Intel Atom® Processors x7000RE Series

- 2 x HDMI® 2.0 output, up to 4096x2160@60Hz
- 1 x DDR5 SO-DIMM, up to 16GB
- 2 x RS-232/422/485, 4 x USB 2.0
- Support M.2 Key B/E/M
- DC 12V~24V power input
- Operating temperature: -20°C~60°C

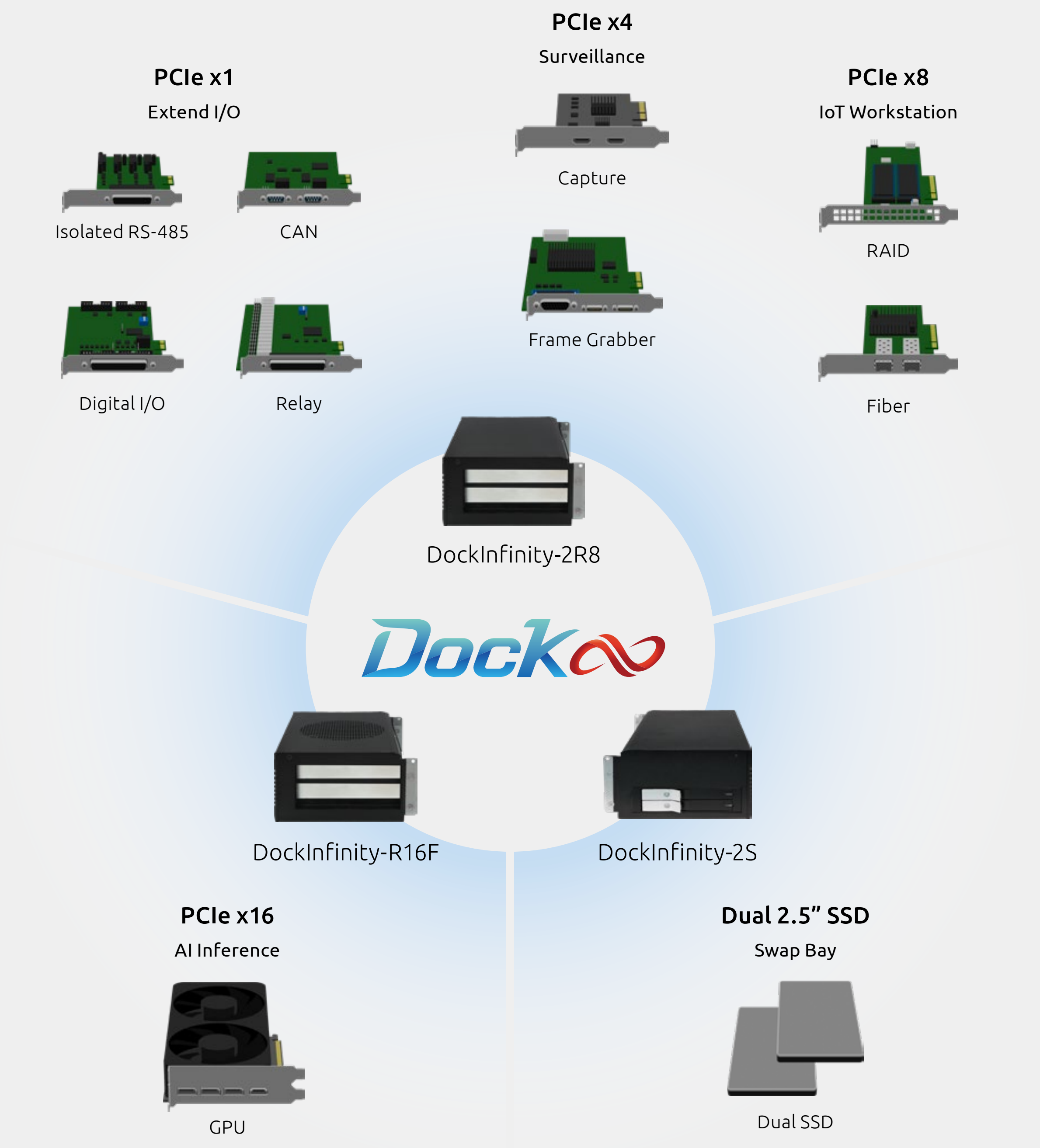
NDiS B340

Duro Edge Computer Powered by Intel Atom® Processors x7000RE Series

- 2 x HDMI® 2.0 output, up to 4096x2160@60Hz
- 1 x DDR5 SO-DIMM, up to 16GB
- 2 x RS-232/422/485, 4 x USB 2.0
- Support M.2 Key B/E/M
- DC 12V~24V power input
- Operating temperature: -20°C~60°C

NDiS B562 w/ Dock∞

Unlimited Expansion. One Powerful Platform.



PCIe x1

Extend I/O

Isolated RS-485

CAN

Digital I/O

Relay

PCIe x4

Surveillance

Capture

Frame Grabber

PCIe x8

IoT Workstation

RAID

Fiber

DockInfinity-2R8

DockInfinity-R16F

DockInfinity-2S

PCIe x16

AI Inference

GPU

Dual 2.5" SSD

Swap Bay

Dual SSD

2026 New Products

Neu-X304 Series

Edge Computing System Powered by 14/13/12th Intel® Core™ i Processor/ Intel® Core™ Processor (Series 2)

- 3 x HDMI® 2.0 output, up to 4096x2160@60Hz
- 4 x USB 3.2, 4 x USB 2.0, 2 x COM port
- 1 x 1GbE LAN, 1 x 2.5GbE LAN, 3 x M.2 Key B/E/M
- Support Intel® AMT technology (Q670E only)
- DC 12V/12~24V (Q670E only) power input
- Operating temperature: -5°C~45°C

Neu-X104-N150

Edge Computing System Powered by Intel® Processor N150

- Slim compact chassis and fanless design
- 1 x DDR4 SO-DIMM, up to 16GB
- 2 x HDMI® 1.4 output, up to 3840x2160@30Hz
- 2 x 2.5GbE LAN, 4 x USB 3.2 Gen 2
- 1 x M.2 Key M for supporting PCIe & SATA storage device
- Operating temperature: -5°C~50°C

Neu-X104-i3

Edge Computing System Powered by Intel® Core™ 3 Processor N355

- Slim compact chassis and fanless design
- 1 x DDR4 SO-DIMM, up to 16GB
- 2 x HDMI® 1.4 output, up to 3840x2160@30Hz
- 2 x 2.5GbE LAN, 4 x USB 3.2 Gen 2
- 1 x M.2 Key M for support PCIe & SATA storage device
- Operating temperature: -5°C~50°C

Neu-XE102-N50-4C

Edge Computing System Power by Intel® Processor N50

- Slim compact and Fanless design
- 1 x DDR4 SO-DIMM up to 16GB
- 2 x HDMI® 1.4 output, up to 3840x2160@30Hz
- 2 x 2.5GbE LAN, 4 x COM port, 3 x USB3.2, 1 x USB 2.0
- 1 x Mini PCIe slot for a Wi-Fi/LTE module
- Operating temperature: -5°C~50°C

Neu-XE102-N97-14C2S

Edge Computing System Powered by Intel® Processor N97

- Slim compact chassis and fanless design
- 1 x DDR4 SO-DIMM, up to 16GB
- 2 x HDMI® 1.4 output, up to 3840x2160@30Hz
- 2 x 2.5GbE LAN, 14 x COM port, 3 x USB3.2, 4 x USB 2.0
- 1 x M.2 Key M 2242 for supporting PCIe storage device
- Operating temperature: -5°C~50°C

SPPC 16-10N150

15.6" TFT FHD 16:9 Slim Bezel Embedded Touchscreen Computer Powered by Intel® Processor N150

- 1 x DDR5 SO-DIMM, up to 16 GB
- 10-point PCAP multi-touch with AF film, thickness only 20mm
- 2 x 2.5GbE LAN, 3 x USB 3.2, 2 x COM port
- 1 x M.2 Key M 2280 for storage
- Operating temperature: 0°C~50°C

XPPC 24-10N97A

23.8" TFT FHD 16:9 Slim Bezel Embedded Touchscreen Computer Powered by Intel® Processor N97

- 1 x DDR4 SO-DIMM, up to 16 GB
- 10-point PCAP touchscreen with slim bezel design
- IP65 protection on the front
- 1 x M.2 Key M 2242, supports PCIe x1 & SATA for storage
- Operating temperature: 0°C~50°C

XPPC 16-10N97

15.6" TFT FHD 16:9 Slim Bezel Embedded Touch Screen Computer Powered by Intel® Processor N97

- 10-point PCAP multi-touch with slim bezel design
- 1 x M.2 2242 Key M, support PCIe x1 & SATA for storage
- 1 x Full-size Mini PCIe for a Wi-Fi/LTE module
- DC 12V power input
- Operating temperature: 0°C~50°C

XPPC 10-10N97

10.1 TFT WXGA 16:10 Slim Bezel Embedded Touch Screen Computer Powered by Intel® Processor N97

- 10-point PCAP multi-touch with slim bezel design
- 1 x M.2 2242 Key M, support PCIe x1 & SATA for storage
- 1 x Full-size Mini PCIe for a Wi-Fi/LTE module
- DC 12V power input
- Operating temperature: 0°C~50°C

HPPC 15-10X7211

15" TFT XGA 4:3 Slim Bezel, High Brightness Panel PC Powered by Intel Atom® X7211RE Processor

- 15" 4:3 ratio 1800 nits sunlight readable panel
- Optical bonding with AF, AG, Anti-UV & IR treatment
- Embedded light sensor for auto-dimming, 2 x Safety fan
- DC 12V~24V power input
- Operating temperature: -20°C~60°C

2026 New Products

HPPC 12-10X7211

12.1” TFT XGA 4:3 Slim Bezel, High Brightness Panel PC Powered by Intel Atom® x7211RE Processor

- 12.1” 4:3 ratio 1300nits sunlight readable panel
- Optical bonding with AF, AG, Anti-UV & IR treatment
- Embedded light sensor for auto-dimming
- DC 12V~24V power input
- Operating temperature: -20°C~60°C

XPPD 24-01

Multi-Touchscreen Display

- 23.8” TFT FHD 16:9 panel, 1920 x 1080, 350cd/m^2
- 1 x HDMI® input
- 1 x USB Type A for touch
- Built-in 2W speaker (optional)
- DC 12V power input
- Operating temperature: 0°C~50°C

X104

3.5” Embedded Computing Board Powered by Intel® Processor N-series & Intel® Core™ Processor N-series

- 1 x DDR4 SO-DIMM socket, up to 16GB
- 2 x HDMI® 2.0 output up to 4K@30Hz, 1 x eDP or LVDS
- 2 x 2.5GbE LAN, 4 x USB 3.2 Gen 2
- 1 x M.2 Key M 2242 for PCIe & SATA storage device
- 1 x Mini PCIe slot for a Wi-Fi/LTE module

X202

3.5” Embedded Computing Board, 13th Gen Intel® Core™ i Processor

- 2 x DDR5 SO-DIMM, up to 96GB
- 2 x HDMI® 1.4 output, up to 4096x2160@30Hz
- 1 x 1GbE LAN, 1 x 2.5GbE LAN
- 1 x USB 3.2 Gen 1x1, 3 x USB 2.0
- 3 x M.2 Key B/E/M
- DC 12V power input

X203

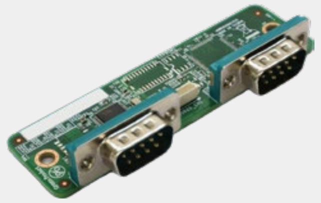
3.5” Embedded Computing Board Powered by Intel® Core™ Ultra Processor (Series 2)

- 2 x DDR5 SO-DIMM, up to 96GB
- 2 x HDMI® 2.0, up to 4096x2160@60Hz
- 1 x 2.5GbE LAN, 1 x 1GbE LAN
- 1 x USB 3.2 Gen 1x1, 3 x USB 2.0
- 3 x M.2 Key B/E/M
- DC 12V power input

X304-MTX

Mini-ITX Embedded Computing Board Powered by 14/13/12th Intel® Core™ i Processor/ Intel® Core™ Processor (Series 2)

- 2 x DDR5 SO-DIMM, up to 64GB
- 3 x HDMI® 2.0, 1 x LVDS (supported by Q670E)
- 1 x 2.5GbE LAN, 1 x 1GbE LAN
- 4 x USB 3.2 (Q670E)/3 x USB 3.2 (H610E), 3 x M.2 Key B/E/M
- DC 12V/12~24V (Q670E only) power input



NTK-USB-2COM

Dual COM Port Expansion Module

- 2 x RS-232/422/485
- Operating temperature: -20°C~85°C
- CE, FCC Class A

NTK-MNE-8COM, NTK-IO-2COM

Multi-Port Serial Expansion Module

- 8 x RS-232
- Operating temperature: -20°C~85°C
- CE, FCC Class A

NTK-MEE-LAN, NTK-IO-RJ45

Gigabit LAN Expansion Module

- 1 x GbE LAN
- Operating temperature: -20°C~85°C
- CE, FCC Class A

Edge Computing System

Smarter Highways Ahead: Empowering ETC Systems with Neu-X302-Q and NDiS B561-PoE for Real-Time Tolling and Vehicle Monitoring

The Background

The highway electronic toll collection (ETC) is an important part of modern transportation and can effectively improve vehicle traffic efficiency. The advanced ETC system, combined with real-time vehicle identification and blacklist monitoring functions, assists the police in tracking down vehicle theft and other illegal activities. The solution combines powerful edge computing, high-speed data processing and reliable device connectivity to ensure seamless operation under harsh highway conditions.

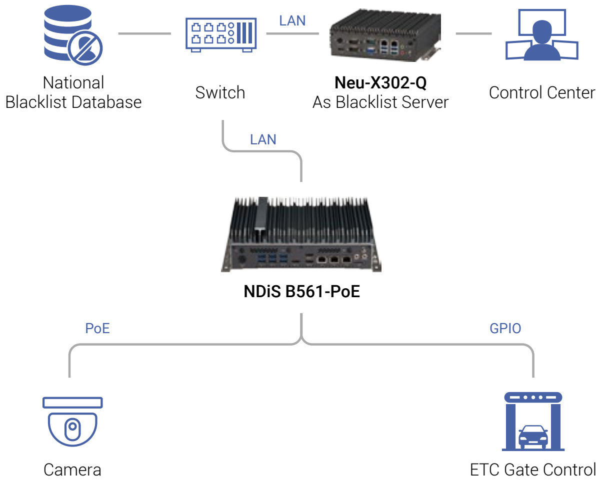
Solution Overview

The ETC system was built using **Neu-X302-Q** as the main computing device and **NDiS B561-PoE** to control the ETC gate and also capture the images through PoE camera. These devices collaborated to deliver robust, real-time data analysis, enabling effective toll management and monitoring.

- **Neu-X302-Q:** The Neu-X302-Q served as the main computing platform for processing vehicle data, running blacklist comparisons, and triggering alerts for unauthorized vehicles. Its fanless design, Intel® 8th/9th Core™ processor, and high I/O expandability made it ideal for 24/7 operation in harsh roadside environments. The device handled large-scale data communication and ensured minimal latency, critical for real-time ETC operations.
- **NDiS B561-PoE:** The NDiS B561-PoE, powered by Intel® 12th Gen Intel® Core™ processor, not only to controls the ETC gate but also captures images of vehicles passing though ETC lane and immediately communicates with the Neu-X302-Q to process the data. Its advanced graphics support allowed seamless real-time visualization, and the PoE functionality significantly reduced wiring complexity by delivering both data and power through a single cable. Its rugged design ensured uninterrupted operations in extreme conditions.

Overall, the deployment of Neu-X302-Q and NDiS B561-PoE revolutionized the highway ETC system, enabling accurate, high-speed toll processing and offering better control over vehicles that attempt to evade tolls or engage in illegal activities. The Neu-X302-Q and NDiS B561-PoE industrial-grade computing devices can transform highway toll collection, paving the way for smarter and safer road infrastructures.

System Architecture



Edge Computing System

Transforming Customer Service with Neu-X302 and AI-based Technology

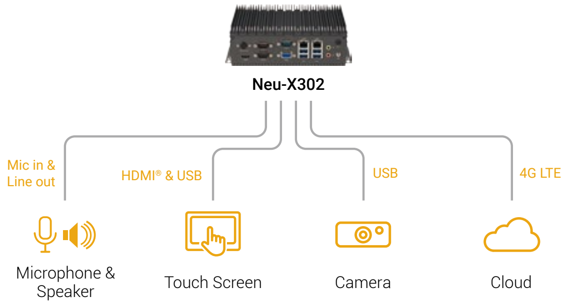
In response to increasing labor shortages and the growing need for efficient, contactless customer interaction, a leading retail solution provider in Asia implemented the Remote Customer Service System, powered by the Neu-X302 fanless edge computing system. This solution offers a new level of digital transformation in customer service through expressive, AI-powered customer interactions and remote human support.

The Remote Customer Service System incorporates an intuitive visual scenario function, allowing operators to design customer guidance paths that combine automated responses with human interaction. The Kiosks, controlled by remote operators, appear on touch-panel screens to provide expressive, face-to-face communication enhanced by AI-driven facial recognition and customer response analysis.

Benefits

The implementation of the Neu-X302 enabled the client to:

- Resolve staffing limitations by centralizing expertise and distributing it virtually across multiple sites.
- Enhance customer satisfaction through more personalized and emotionally intelligent interactions.
- Digitize and automate large parts of the customer service workflow, reducing human resource strain.
- Gain real-time insights through scenario usage data, occupancy rates, and customer feedback, supporting continuous improvement via PDCA cycles.
- Ensure privacy compliance, with control over data storage and recording features.



Why Neu-X302?

The customer selected the Neu-X302 for its compact, fanless design, ensuring quiet operation in public-facing environments, and industrial-grade reliability. Its processing power supports real-time video and AI capabilities, while flexible connectivity options (USB, SIM, audio I/O) support the varied needs of the customer service interface system. The platform's edge computing capacity reduces latency and improves responsiveness, critical for fluid customer interactions.

By integrating the Neu-X302, the client successfully elevated their customer service experience—delivering innovative, efficient, non-contact, face-to-face and satisfying service in an increasingly digital world.

System Architecture

At the heart of the system lies the Neu-X302, equipped with an 9/8th Gen Intel® Core™ processor and Intel® Q370 chipset. This robust edge computing platform integrates seamlessly with essential peripherals—HDMI® output, camera, microphone, speaker, and SIM-based connectivity—to enable real-time, two-way visual and audio communication. The architecture connects the customer's device to the cloud for centralized data analysis, while maintaining customer privacy by allowing recording to be locally disabled.

Neu-X302

- Support 9/8th Gen Intel® Core™ i processors
- Dual channel DDR4 SO-DIMM, up to 32GB
- 1 x VGA and 1 x HDMI® 1.4 4K display outputs
- Onboard M.2 Key B/E for storage and wireless connection
- Dual Intel® LAN ports
- 6 x COM port, 10 x USB, 1 x Mic in, 1 x Line out
- TPM 2.0 design for security advantage
- Support Intel® AMT technology

Edge Computing System

Neu-X102-N50 Powers Automated Garment Management in Hospitals

Background

Hospitals operate around the clock, and medical staff require continuous access to clean scrubs and uniforms. Traditional garment rooms that rely on manual distribution often struggle with stock accuracy, garment traceability, and high labor costs.

To address these challenges, healthcare providers are increasingly turning to automated dispensing and return cabinets. These systems ensure that fresh garments are always available while providing secure return points for used items. By automating the process, hospitals gain tighter control over garment circulation, reduce operational overhead, and maintain higher compliance with hygiene standards.

The Challenge

In such automated garment cabinet systems, the control unit must meet multiple requirements:

- **Compact size** to fit within limited cabinet space
- **Industrial reliability** to ensure 24/7 uptime in a hospital setting
- **Peripheral connectivity** to support barcode/RFID readers, printers, and touch displays
- **Network connectivity** for integration with hospital IT systems and remote management consoles
- **Cost efficiency** without sacrificing performance

The cabinet builder required a gateway controller that could run their HMI software, seamlessly manage multiple devices, and provide a stable, long-life platform.

The Solution – NEXCOM Neu-X102-N50

NEXCOM's Neu-X102-N50 fanless embedded system was chosen as the controller for the hospital's automated garment cabinets. The system is mounted inside the cabinet and serves as the gateway between hospital staff, garment inventory, and the management platform.

System Integration Highlights:

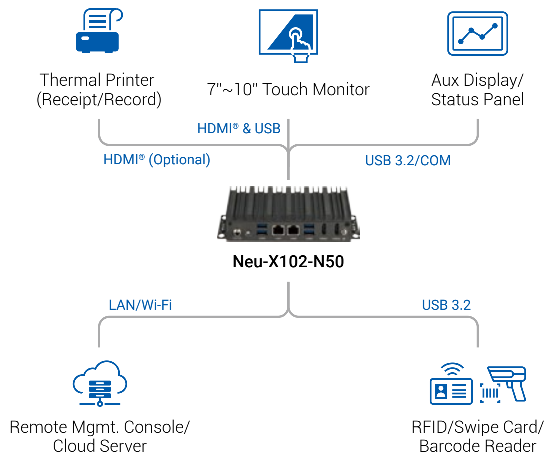
- **HDMI® + USB:** Connects to a 7"–10" touch monitor for intuitive garment selection and return interface
- **COM Port:** Connects to a thermal printer for issuing receipts or garment usage records
- **USB Ports:** Supports multiple peripherals such as RFID readers, swipe card readers, and barcode scanners
- **Wi-Fi/LAN:** Provides remote management capability, enabling IT staff to monitor system health, update software, and manage cabinet usage data centrally

Customer Benefits

- **Compact and Fanless:** The slim design and quiet operation fit perfectly into the confined space of the cabinet while ensuring reliability in 24/7 hospital operations.
- **Performance at the Right Price:** Powered by Intel® processor N50, the Neu-X102-N50 delivers the right balance of performance and aggressive pricing, making large-scale deployment cost-effective.
- **Flexible Connectivity:** Multiple I/O interfaces allow easy integration of different peripheral devices essential for garment management.
- **Remote Control and Monitoring:** Network connectivity enables centralized system oversight and reduces the need for onsite service.
- **Future-Proof Investment:** Industrial-grade design and long lifecycle support make the solution a sustainable investment for healthcare providers.

Conclusion

By integrating **NEXCOM Neu-X102-N50** into automated garment cabinet solutions, hospitals gain a reliable, compact, and cost-efficient gateway controller that streamlines uniform management. With its rich connectivity, performance efficiency, and long-term availability, the Neu-X102-N50 helps hospitals improve hygiene compliance, enhance staff convenience, and optimize operational costs.



Duro Edge Computer

NEXCOM Empowers Automobile Manufacturers in Data Collection from Production Line to Customer Insights

Challenges

In today's fast-paced logistics environment, accuracy and efficiency are critical to maintaining profitability and customer satisfaction. For third-party logistics (3PL) providers, postal operators, and freight companies, the ability to quickly and precisely measure the dimensions, volume, and weight of items directly impacts space utilization, billing accuracy, and delivery efficiency.

However, many organizations still rely on manual measurement methods—time-consuming and prone to error—leading to inaccurate data, delayed operations, and lost revenue opportunities.

Solutions

To overcome these challenges, a powerful data capture and management system is designed and introduced to streamline dimensioning operations. NDiS B561 serves as a central intelligence hub, connecting seamlessly with dimensioning devices to collect, validate, and distribute accurate item data.

The system captures dimensional, volumetric, and weight information in real time, storing it securely and sharing it with warehouse management system (WMS), transport management system (TMS), and billing systems through flexible APIs and communication protocols. Its robust architecture ensures reliable data transmission and storage, even in high-volume or network-limited environments.

Why NDiS B561?

NEXCOM's **NDiS B561** is an ideal system for integration into Dimensioning, Weighing, and Scanning (DWS) solutions due to its **high-performance computing power, robust connectivity,** and **industrial-grade reliability**. Powered by the 13/12th Gen Intel® Core™ i processor, it can efficiently process real-time image, weight, and dimension data from multiple sensors, ensuring fast and accurate measurements. Its rich I/O interfaces support seamless integration with cameras, barcode scanners, and weighing modules, while its **fanless and durable design** ensures stable operation in warehouse and logistics environments.

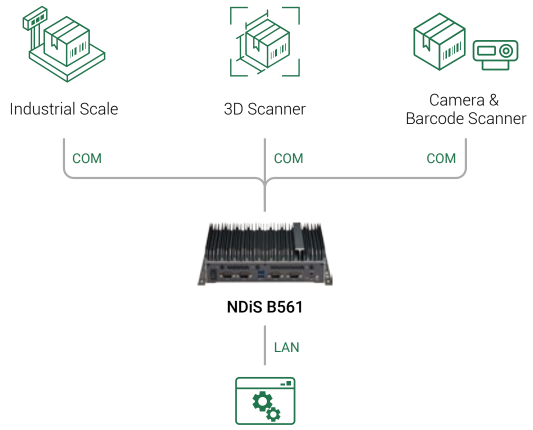
Implementation and Results

This **NDiS B561 integrated Dimensioning Solution** has been successfully deployed by leading postal and transport companies to modernize their parcel handling operations. By replacing manual measurement with automated dimensioning, these organizations achieved:

- **Faster processing speeds:** Measurement time per item reduced from several seconds to less than one second, increasing daily throughput.
- **Higher accuracy:** Data errors and rework rates decreased significantly, improving operational consistency.
- **Improved billing precision:** Accurate dimensional data ensured proper freight charges and eliminated revenue leakage.
- **Seamless integration:** NDiS B561 easily connected with existing enterprise systems, avoiding major infrastructure changes.
- **Future scalability:** Its modular design allows new stations and devices to be added as business needs expand.

Conclusion

The NDiS B561 integrated Dimensioning, Weighing, and Scanning System empowers logistics and shipping companies with a fast, accurate, and scalable dimensioning solution. By bridging measurement hardware and enterprise systems, customers are enabled to optimize performance, enhance visibility, and move toward a data-driven logistics future.



Edge AI Computing System

Transforming Campus Administration and Services with School AI Management System

Background

Traditional paper-based school administration processes are time-consuming, inefficient, and prone to human error. Furthermore, IT departments often need to build customized software from scratch, which introduces security risks and creates unnecessary overhead. Many schools also rely on public cloud services, which can expose sensitive student data to higher cybersecurity threats.

Challenges

- **Inefficient paper workflows** slowing down data management.
- **IT resource burden**, requiring self-developed tools.
- **Cybersecurity concerns,** especially with public cloud reliance.
- **Network connectivity** for integration with hospital IT systems and remote management consoles.
- **High setup time,** delaying project go-live.

To address these challenges, a national senior high school in Taiwan sought an AI-powered solution powered by NEXCOM that could integrate existing platforms, improve user experience, and ensure data privacy within its internal network.

This integrated system connects with the school's library, academic affairs, internship, continuing education, counseling, and general affairs departments through APIs. Data is seamlessly collected, cleaned, and updated across platforms—including printed documents—ensuring synchronized and secure operations.

System Architecture

The solution integrates **AI inference and microservices computing** on AIEdge-X®310 with **customized EdgeGPT services** powered by Neu-X60.

- **AIEdge-X®310 (RAG/LLM Server):** Provides high-performance AI computation, enabling retrieval-augmented generation (RAG), prompt-based services, and multi-agent AI applications.
- **Neu-X60 (Query Server):** Acts as the localized large language model platform, ensuring secure, on-premises knowledge retrieval and natural language interaction.
- **Neu-X102-N50 (MCP):** Connected via USB hub for data collection.

Why AIEdge-X®310 and Neu-X60?

NEXCOM's solution was chosen because it uniquely combines **industrial-grade AI hardware** with a **localized LLM platform,** ensuring **privacy, reliability, and adaptability.**

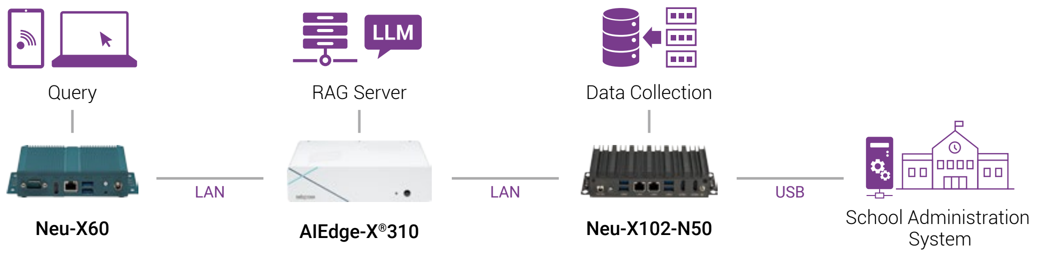
To this National Senior High School, the deployment not only modernized campus operations but also demonstrated how AI can be securely and effectively applied in education and public sector administration.

By leveraging **AIEdge-X®310 and Neu-X60**, the school has taken a significant step toward building a **smart campus**, setting a strong example of how AI-powered solutions can transform traditional institutions.

Customer Benefits

The integration of **AIEdge-X®310, Neu-X60, and Neu-X102-N50** delivers several key benefits:

- **Enhanced Efficiency:** Staff and students access information instantly through conversational AI, reducing manual workload.
- **Data Security:** On-premises EdgeGPT ensures sensitive academic and administrative data never leaves the intranet.
- **Cost Savings:** One-time licensing lowers recurring fees compared to cloud-based AI services.
- **Scalable Deployment:** AI microservices architecture allows expansion to additional systems such as ERP, BPM, MES, CRM, and PLM.
- **User-friendly Experience:** Voice input and natural language queries simplify interactions for non-technical users.



Duro Edge Computer

Urban PET Recycling Reinvented: Sustainable Solutions Powered by NDiS B561

Background

PET bottles can remain in the environment for decades, contributing to ocean pollution, carbon emissions, and growing urban waste. Recycling is essential to reduce these impacts and return valuable materials to the circular economy, supporting long-term sustainability. Innovative **PET recycling machines** installed on sidewalks make recycling convenient and accessible, combining technology with environmental responsibility. By encouraging habitual recycling, these automated kiosks help cities increase recycling rates, lower carbon footprints, and move toward a zero-waste future.

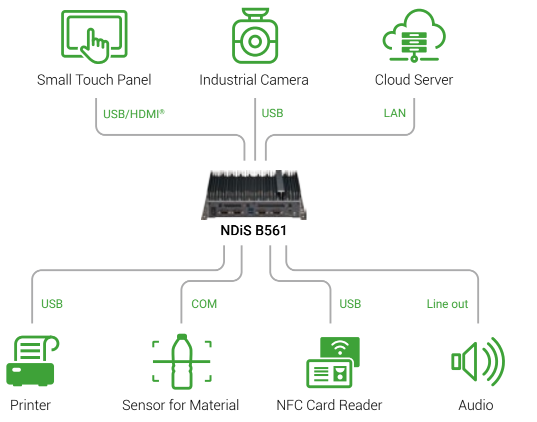
The Challenge

Urban environment — like the city street scene with narrow sidewalks, mixed traffic, and possible exposure to varying weather and temperature — the system must contend with:

- **Extreme temperature swings:** Outdoor installations face harsh seasonal changes, from freezing winters to hot summers.
- **Limited installation space:** Sidewalk locations often provide minimal room for equipment, making compact integration essential.
- **Demand for reliable processing and connectivity:** Machines must handle sensor data, user interfaces, remote monitoring, and stable communication under continuous public use.

The Solution – NEXCOM NDiS B561

- The fanless and passively-cooled design reduces maintenance and potential failure, ensuring long-term reliability even outdoors.
- Support for 24V DC input allows easy integration into existing power infrastructure typical for recycling machines.
- With dimensions of 238mm (W) x 190mm (D) x 67.1mm (H), its form factor simplifies installation in limited space enclosures.
- Rich I/O connectivity enables interface display, data processing, network communication, and peripheral control.



System Integration Highlights

- **USB 3.2 ports** connect industrial cameras for bottle identification, touch panels for enhanced user interaction, and printers for receipts.
- **COM ports** ensure precise communication with material sensors for accurate sorting and logging.
- **HDMI® 2.1 output** drives screens to display recycling instructions and promotional advertisements.
- **Multiple Gigabit LAN ports** (supporting 4G/5G) guarantee the instantaneous and secure transfer of operational data—such as bin capacity and transaction history—straight to the cloud.

Conclusion

This successful case demonstrates how combining a PET recycling machine with the NDiS B561 creates a practical, sustainable, and smart urban recycling solution. Thanks to the NDiS B561's stability, reliability, and flexibility, the recycling machine can operate dependably on city streets — realizing the vision of smart recycling, sustainable cities, and moving toward a zero-waste future.

NDiS B561

- Support 13/12th Gen Intel® Core™ i9/i7/i5/i3 processor
- Intel® PCH Q670E
- Intel® UHD Graphics 730/770 (i5 and above)
- 1 x HDMI® 2.1, up to 8K@60Hz
- 2 x HDMI® 2.0, up to 4K@60Hz
- 8 x USB 3.2
- 1 x RS-232/422/485, 3 x RS-232
- 1 x GbE LAN, 2 x 2.5GbE LAN
- 3 x M.2 Key B/E/M

Edge Computing System

Model	 Neu-X100	 Neu-X101	 Neu-X101-6C-DC
CPU	- Intel® Pentium® processor N4200, TDP 6W - Intel® Celeron® processor J3455/ N3350, TDP 10W/6W	Intel® Celeron® processor J3455, TDP 10W	Intel® Celeron® processor J3455, TDP 10W
Chipset	-	-	-
Graphics	- Intel® HD Graphics 505 (N4200) - Intel® HD Graphics 500 (J3455/N3350)	Intel® HD Graphics 500	Intel® HD Graphics 500
Memory	1 x DDR3L SO-DIMM, up to 8GB	1 x DDR3L SO-DIMM, up to 8GB	1 x DDR3L SO-DIMM, up to 8GB
Gigabit LAN	2	2	2
WLAN	Option	Option	-
Hard Disk Interface	-	-	-
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0)	1 x M.2 Key M 2242 (SATA 3.0)	1 x M.2 Key M 2242 (SATA3.0)
Display Output	2 x HDMI® 2.0	2 x HDMI® 1.4b	2 x HDMI® 1.4b
Max. Display Resolution	4096x2160@60Hz	3840x2160@30Hz	3840x2160@30Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 - 4 x RS-485
USB 2.0	4 (internal)	- 2 - 2 (internal)	- 2 - 2 (internal)
USB 3.2	2	2	2
Expansion Slot	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	-
Operating Temp.	-5°C~50°C	-5°C~50°C	-5°C~50°C
Power Input	DC 19V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 9V~24V
Dimensions W x D x H (mm)	179.5 x 106 x 37	179.5 x 106 x 37	179 x 121 x 44
OS Support	Win 10/Linux	Win 10/Linux	Win 10/Linux
Gross Weight (kg)	1.48	1.5	1.48
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Model	 Neu-X102-N50	 Neu-X102-N97	NEW  Neu-X1025-N50
CPU	Intel® processor N50, TDP 6W	Intel® processor N97, TDP 12W	Intel® processor N50, TDP 6W
Chipset	-	-	-
Graphics	Intel® UHD Graphics	Intel® UHD Graphics	Intel® UHD Graphics
Memory	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR5 SO-DIMM, up to 16GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	-
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)
Display Output	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)
Max. Display Resolution	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)
USB 2.0	2 (internal)	2 (internal)	2 (internal)
USB 3.2	4	4	4
Expansion Slot	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)
Operating Temp.	-5°C~50°C	–5°C~50°C	-5°C~50°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	179.5 x 106 x 37	203.5 x 106 x 40	179.5 x 106 x 37
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Gross Weight (kg)	1.5	1.6	1.5
Certifications	CE, FCC Class B, UL	CE, FCC Class B, UL	CE, FCC Class B, UL

Edge Computing System

Model	NEW  **Neu-X1025-N97**	NEW  **Neu-X104-N150**	NEW  **Neu-X1045-N150**
CPU	Intel® processor N97, TDP 12W	Intel® processor N150, PBP 6W	Intel® processor N150, PBP 6W
Chipset	-	-	-
Graphics	Intel® UHD Graphics	Intel® Graphics, up to 32EU w/ INT8 extension	Intel® Graphics, up to 32EU w/ INT8 extension
Memory	1 x DDR5 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR5 SO-DIMM, up to 16GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	-
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)
Display Output	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)
Max. Display Resolution	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)
USB 2.0	2 (internal)	2 (internal)	2 (internal)
USB 3.2	4	4	4
Expansion Slot	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)
Operating Temp.	-5°C~50°C	-5°C~50°C	-5°C~50°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	203.5 x 106 x 40	179.5 x 106 x 37	179.5 x 106 x 37
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Gross Weight (kg)	1.6	1.5	1.5
Certifications	CE. FCC Class B, UL	CE, FCC Class B, UL	CE, FCC Class B, UL

Model	 **Neu-X60**	NEW  **Neu-X61**	NEW  **Neu-XE102-N50-4C**	NEW  **Neu-XE102-N97-6C2S**
CPU	Intel® Processor N50, TDP 6W	Intel® processor N150, PBP 6W	Intel® Processor N50, TDP 6W	IIntel® processor N97, TDP 12W
Chipset	-	-	-	-
Graphics	Intel® UHD Graphics	Intel® Graphics, up to 32EU w/ INT8 extension	Intel® UHD Graphics	Intel® UHD Graphics
Memory	1 x DDR4 SO-DIMM, default 4GB, up to 16GB	1x DDR5 SO-DIMM, up to 16GB	1x DDR4 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB
Gigabit LAN	1	2	2	2
WLAN	Option	Option	Option	Option
Hard Disk Interface	-	-	-	2 x SATA 3.0
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0/ PCIe 3.0 x4), default 128GB	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x4)	1 x M.2 Key M 2242 (PCIe 3.0 x1)	- 1 x M.2 Key M 2242 (PCIe 3.0 x1) - 2 x 2.5" SSD tray
Display Output	1 x HDMI® 1.4	1 x HDMI® 1.4	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)
Max. Display Resolution	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz
Output Channel	1	1	2 independent or clone	2 independent or clone
Audio I/O	1 x Line out (internal)	- 1 x Line out - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232 - 1 x RS-232 (internal)	- 2 x RS-232/422/485 - 2 x RS-232 - 2 x RS-232 (internal)	- 2 x RS-232/422/485 - 4 x RS-232
USB 2.0	2 (internal)	2 (internal)	- 1 - 3 (internal)	4
USB 3.2	2	2	3	3
Expansion Slot	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)
Operating Temp.	0°C~40°C	0°C~40°C	-5°C~50°C	-5°C~50°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	156 x 119.6 x 31	156 x119.6 x 31	203.5 x 132 x 40 (w/ bracket)	203 x 137 x 95 (w/ bracket)
OS Support	Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Gross Weight (kg)	1.32	1.32	1.87	2.46
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Edge Computing System

Model	NEW  Neu-XE102-N97-14C2S	NEW  Neu-XE104-N150-6C2S	NEW  Neu-XE104-N150-14C2S
CPU	IIntel® processor N97, TDP 12W	Intel® processor N150, PBP 6W	Intel® processor N150, PBP 6W
Chipset	-	-	-
Graphics	Intel® UHD Graphics	Intel® Graphics, up to 32EU w/ INT8 extension	Intel® Graphics, up to 32EU w/ INT8 extension
Memory	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	2 x SATA 3.0	2 x SATA 3.0	2 x SATA 3.0
Flash Storage	- 1 x M.2 Key M 2242 (PCIe 3.0 x1) - 2 x 2.5" SSD tray	- 1 x M.2 Key M 2242 (PCIe 3.0 x1) - 2 x 2.5" SSD tray	- 1 x M.2 Key M 2242 (PCIe 3.0 x1) - 2 x 2.5" SSD tray
Display Output	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)
Max. Display Resolution	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 2 x RS-232/422/485 - 12 x RS-232	- 2 x RS-232/422/485 - 4 x RS-232	- 2 x RS-232/422/485 - 12 x RS-232
USB 2.0	4	4	4
USB 3.2	3	3	3
Expansion Slot	Pre-installed w/ one Mini PCIe card (NTK-MNE-8COM)	1 x Mini PCIe (SIM slot)	Pre-installed w/ one Mini PCIe card (NTK-MNE-8COM)
Operating Temp.	-5°C~50°C	-5°C~50°C	-5°C~50°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	203 x 137 x 95 (w/ bracket)	203 x 137 x 95 (w/ bracket)	203 x 137 x 95 (w/ bracket)
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Gross Weight (kg)	2.53	2.46	2.53
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Model	 Neu-X102-i3	NEW  Neu-X1025-N305	NEW  Neu-X104-i3	NEW  Neu-X1045-N355
CPU	Intel® Core™ i3-N305 processor, TDP 15W	Intel® Core™ i3-N305 processor, TDP 15W	Intel® Core™ 3 processor N355, PBP 15W	Intel® Core™ 3 processor N355, PBP 15W
Chipset	-	-	-	-
Graphics	Intel® UHD Graphics	Intel® UHD Graphics	Intel® Graphics, up to 32EU w/ INT8 extension	Intel® Graphics, up to 32EU w/ INT8 extension
Memory	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR5 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR5 SO-DIMM, up to 16GB
Gigabit LAN	2	2	2	2
WLAN	Option	Option	Option	Option
Hard Disk Interface	-	-	-	-
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)
Display Output	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)	- 2 x HDMI® 1.4 - 1 x eDP/LVDS (internal)
Max. Display Resolution	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone	2 independent or clone
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)
USB 2.0	2 (internal)	2 (internal)	2 (internal)	2 (internal)
USB 3.2	4	4	4	4
Expansion Slot	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)
Operating Temp.	-5°C~50°C	-5°C~50°C	-5°C~50°C	-5°C~50°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	203.5 x 106 x 40	203.5 x 106 x 40	203.5 x 106 x 40	203.5 x 106 x 40
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Gross Weight (kg)	1.6	1.6	1.6	1.6
Certifications	CE, FCC Class B, UL	CE, FCC Class B, UL	CE, FCC class B, UL	CE, FCC class B, UL

Edge Computing System

Model	 **Neu-X300**	 **Neu-X302**
CPU	8th Gen Intel® Core™ i processor, TDP 35W	9/8th Gen Intel® Core™ i processor, TDP 35W
Chipset	Intel® PCH Q370/H310	Intel® PCH Q370/H310
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 630
Memory	2 x DDR4 SO-DIMM, up to 32GB	2 x DDR4 SO-DIMM, up to 32GB
Gigabit LAN	2	2
WLAN	Option	Option
Hard Disk Interface	-	1 x SATA 3.0
Flash Storage	1 x M.2 Key M 2280 - Q370: SATA 3.0/PCIe 3.0 x4 - H310: SATA 3.0 only	1 x M.2 Key M 2242/3042 - Q370: PCIe 3.0 x1/SATA 3.0/USB 3.2 - H310: SATA 3.0 only, USB 2.0 if 3G/4G module not in use
Display Output	- 3 x HDMI® 2.0 (Q370) - 2 x HDMI® 2.0 (H310)	- 1 x VGA - 1 x HDMI® 1.4 - 1 x LVDS (internal)
Max. Display Resolution	4096x2160@60Hz	4096x2160@30Hz
Output Channel	3 independent or clone	2 independent or clone
Audio I/O	- 1 x Line out - 1 x Mic in (internal)	- 1 x Line out - 1 x Mic in - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 2 x RS-232 (internal)	- 3 x RS-232/422/485 - 3 x RS-232
USB 2.0	6 (internal, Q370)/2 (internal, H310)	6 (internal, Q370)/3 (internal, H310)
USB 3.2	4	4
Expansion Slot	1 x M.2 Key E 2230	1 x M.2 Key E 2230
Operating Temp.	-5°C~45°C	-5°C~45°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	190 x 200 x 54.4	190 x 200 x 64.3
OS Support	Win 10/Linux	Win 10/Linux
Gross Weight (kg)	3.61	3.97
Certifications	CE, FCC Class A	CE, FCC Class A

Product appearance and specifications are subject to change without notice.

Model	 **Neu-X303**	 **Neu-X303mini**	NEW  **Neu-X304**
CPU	12th Gen Intel® Core™ i processor, TDP 15W	12th Gen Intel® Core™ i processor, PBP 45W	14/13/12th Gen Intel® Core™ i processor/ Intel® Core™ processor (Series 2), PBP 45W
Chipset	-	-	Intel® PCH Q670E/H610E
Graphics	Intel® Iris® X^e Graphics (on i5/i7)/ Intel® UHD Graphics 730 (on i3)	Intel® Iris® X^e Graphics (on i5/i7)/ Intel® UHD Graphics 730 (on i3)	Intel® UHD Graphics 770
Memory	2 x DDR5 SO-DIMM, up to 64GB	2 x DDR5 SO-DIMM, up to 64GB	2 x DDR5 SO-DIMM, up to 64GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	1 x SATA 3.0
Flash Storage	1 x M.2 Key M 2280 (PCIe 3.0 x4)	1 x M.2 Key M 2280 (PCIe 3.0 x4)	1 x M.2 Key M 2280 (SATA 3.0/PCIe 4.0 x4)
Display Output	- 1 x HDMI® 2.1 - 1 x DP 1.4 - 2 x DP 1.4 (thru USB Type-C)	- 1 x HDMI® 2.1 - 1 x DP 1.4 - 2 x DP 1.4 (thru USB Type-C)	- 3 x HDMI® 2.0 - 1 x eDP/LVDS (internal)
Max. Display Resolution	7680x4320@60Hz	7680x4320@60Hz	4096x2160@60Hz
Output Channel	4 independent or clone	4 independent or clone	3 independent or clone
Audio I/O	-	-	- 1 x Line out - 1 x Mic in
COM Port	1 x RS-232 (internal)	1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232
USB 2.0	1 (internal)	1 (internal)	4 (Q670E)/ 5 (internal, H610E)
USB 3.2	6 (2 thru USB Type-C)	6 (2 thru USB Type-C)	4 (Q670E)/3 (H610E)
Expansion Slot	1 x M.2 Key E 2230	1 x M.2 Key E 2230	- 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052
Operating Temp.	0°C~50°C	0°C~60°C	-5°C~45°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V~24V (Q670E)/DC 12V (H610E), incl. AC/DC power adapter
Dimensions W x D x H (mm)	215 x 150 x 65.9	183 x 137.9 x 47.9	210 x 210 x 50
OS Support	Win 10/Linux	Win 10/Linux	Win 11/Win 10/Linux
Gross Weight (kg)	3.05	3.25	3.9
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Product appearance and specifications are subject to change without notice.

Duro Edge Computer

Model	 **NDiS B560-Q**	 **NDiS B561**
CPU	9/8th Gen Intel® Core™ i processor, TDP 35W	14/13/12th Gen Intel® Core™ i processor, TDP 35W
Chipset	Intel® PCH Q370	Intel® PCH Q670E
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 770
Memory	2 x DDR4 SO-DIMM, up to 32GB	2 x DDR5 SO-DIMM, up to 64GB
Gigabit LAN	2	3
WLAN	Option	Option
Hard Disk Interface	1 x SATA 3.0	-
Flash Storage	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4)	- 1 x M.2 Key M 2280 (PCIe 3.0 x4) - 1 x M.2 Key M 2280 (SATA 3.0)
Display Output	3 x HDMI® 2.0	- 1 x HDMI® 2.1 - 2 x HDMI® 2.0
Max. Display Resolution	4092x2160@60Hz	- HDMI® 2.1: 7680x4320@60Hz - HDMI® 2.0: 4096x2160@60Hz
Audio I/O	- 1 x Line out - 1 x Mic in	- 1 x Line out - 1 x Mic in - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 3 x RS-232	- 1 x RS-232/422/485 - 3 x RS-232
USB 2.0	-	4 (internal)
USB 3.2	6	8
Expansion Slot	- 1 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052	- 2 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052
Operating Temp.	-20°C~60°C	-20°C~60°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V~24V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	238 x 192 x 67.3	268 x 190 x 73.7
OS Support	Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	3.5	3.9
Gross Weight (kg)	5.0	4.9
Certifications	CE, FCC Class A	CE, FCC Class A

Model	 **NDiS B561-PoE**	NEW  **NDiS B562**
CPU	14/13/12th Gen Intel® Core™ i processor, TDP 35W	- 14/13/12th Gen Intel® Core™ i processor, PBP 35W - Intel® Core™ processor (Series 2), TDP 45W
Chipset	Intel® PCH Q670E	Intel® PCH H610E
Graphics	Intel® UHD Graphics 770	Intel® UHD Graphics 770
Memory	2 x DDR5 SO-DIMM, up to 64GB	2 x DDR5 SO-DIMM, up to 96GB
Gigabit LAN	3 (including 2 PoE ports)	3
WLAN	Option	Option
Hard Disk Interface	-	2 x SATA 3.0
Flash Storage	- 1 x M.2 Key M 2280 (PCIe 3.0 x4) - 1 x M.2 Key M 2280 (SATA 3.0)	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4)
Display Output	- 1 x HDMI® 2.1 - 2 x HDMI® 2.0	- 2 x DP 1.2 - 1 x HDMI® 2.0
Max. Display Resolution	- HDMI® 2.1: 7680x4320@60Hz - HDMI® 2.0: 4096x2160@60Hz	- DP 1.2: 4096x2160@60Hz - HDMI® 2.0: 4096x2160@60Hz
Audio I/O	- 1 x Line out - 1 x Mic in - 1 x Speaker (internal)	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 3 x RS-232	- 2 x RS-232/422/485 - 4 x RS-232 (internal)
USB 2.0	4 (internal)	1
USB 3.2	8	3
Expansion Slot	- 2 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052	- 1 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052
Operating Temp.	0°C~40°C	-20°C~60°C
Power Input	DC 12V~24V, incl. AC/DC power adapter	DC 12V~24V
Dimensions W x D x H (mm)	268 x 190 x 73.7	268.4 x 190.6 x 75.4
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	3.9	3.0
Gross Weight (kg)	4.9	4.1
Certifications	CE, FCC Class A	CE, FCC Class A

Duro Edge Computer

Model	 NEW **NDiS B562-Q-2R8/-R16F**	 NEW **NDiS B562-Q-2S**
CPU	- 14/13/12th Gen Intel® Core™ i processor, PBP 35W - Intel® Core™ processor (Series 2), TDP 45W	- 14/13/12th Gen Intel® Core™ i processor, PBP 35W - Intel® Core™ processor (Series 2), TDP 45W
Chipset	Intel® PCH Q670E/H610E	Intel® PCH Q670E
Graphics	Intel® UHD Graphics 770	Intel® UHD Graphics 770
Memory	2 x DDR5 SO-DIMM, up to 96GB	2 x DDR5 SO-DIMM, up to 96GB
Gigabit LAN	3	3
WLAN	Option	Option
Hard Disk Interface	-	2 x SATA 3.0
Flash Storage	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4)	- 1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4) - 2 x 2.5" SSD bay
Display Output	- 2 x DP 1.2 - 1x HDMI® 2.0	- 2 x DP 1.2 - 1x HDMI® 2.0
Max. Display Resolution	- DP 1.2: 4096x2160@60Hz - HDMI® 2.0: 4096x2160@60Hz	- DP 1.2: 4096x2160@60Hz - HDMI® 2.0: 4096x2160@60Hz
Audio I/O	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 2 x RS-232/422/485 - 4 x RS-232 (internal)	- 2 x RS-232/422/485 - 4 x RS-232 (internal)
USB 2.0	2 (Q670E)/1 (H610E)	2
USB 3.2	3	3
Expansion Slot	- 1 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052 - 2 x PCIe x8 (Q670E)/1 x PCIe x16 (H610E)	- 1 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052
Operating Temp.	0°C~40°C	-20°C~60°C
Power Input	DC 12V~24V	DC 12V~24V
Dimensions W x D x H (mm)	388.6 x 190.6 x 75.4	388.6 x 190.6 x 75.4
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	3.7	4.0
Gross Weight (kg)	4.7	5.0
Certifications	CE, FCC Class A	CE, FCC Class A

Model	 **NDiS B560S-H**	 **NDiS B561S**	 **NDiS B360**
CPU	9/8th Gen Intel® Core™ i processor, TDP 35W	14/13/12th Gen Intel® Core™ i processor, PBP 35W	11th Gen Intel® Core™ i processor, TDP 15W
Chipset	Intel® PCH H310	Intel® PCH H610E	-
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 770	- Intel® Iris® X^e Graphics (on i5) - Intel® UHD Graphics (on i3)
Memory	2 x DDR4 SO-DIMM, up to 32GB	2 x DDR5 SO-DIMM, up to 64GB	1 x DDR4 SO-DIMM, up to 32GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	1 x SATA 3.0	-	-
Flash Storage	1 x M.2 Key M 2280 (SATA 3.0)	- 1 x M.2 Key M 2280 (PCIe 4.0 x4) - 1 x M.2 Key M 2280 (SATA 3.0)	1 x M.2 Key M 2280 (PCIe 3.0 x4)
Display Output	2 x HDMI® 2.0	2 x HDMI® 2.0	- 1 x DP++ - 1 x HDMI® 2.0
Max. Display Resolution	4096x2160@60Hz	4096x2160@60Hz	- DP++: 4096x2304@60Hz - HDMI® 2.0: 4096x2160@60Hz
Audio I/O	- 1 x Line out - 1 x Mic in	- 1 x Line out - 1 x Mic in - 1 x Speaker (internal)	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 3 x RS-232	- 1 x RS-232/422/485 - 3 x RS-232	- 1 x RS-232/422/485 - 1 x RS-232
USB 2.0	2	4	4 (internal)
USB 3.2	4	2	4
Expansion Slot	- 1 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052	- 2 x M.2 Key M 2280 - 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052	1 x M.2 Key E 2230
Operating Temp.	0°C~40°C	0°C~50°C	-20°C~60°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	238 x 192 x 39	238 x 192 x 39	200 x 132.6 x 36
OS Support	Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	2.6	2.6	1.3
Gross Weight (kg)	4.0	3.9	2.0
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A, UL

Duro Edge Computer

Model	NEW  **NDiS B361**	 **NDiS B362**	NEW  **NDiS B363**
CPU	13th Gen Intel® Core™ i processor, PBP 15W	Intel® Core™ Ultra processor (Series 1), PBP 15W	Intel® Core™ Ultra 7/5 processor (Series 2), PBP 15W
Chipset	-	-	-
Graphics	- Intel® Iris® X^e LPG Graphics (on i7, i5) - Intel® UHD Graphics (on i3)	Intel® Graphics	Intel® Graphics
Memory	2 x DDR5 SO-DIMM, up to 96GB	2 x DDR5 SO-DIMM, up to 96GB	2 x DDR5 SO-DIMM, up to 96GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	-
Flash Storage	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4)	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4)	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4)
Display Output	2 x HDMI® 1.4	2 x HDMI® 2.0	2 x HDMI® 2.0
Max. Display Resolution	4096x2160@30Hz	4096x2160@60Hz	4096x2160@60 Hz
Audio I/O	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	2 x RS-232/422/485	2 x RS-232/422/485	- 1 x RS-232/422/485 - 1 x RS-232
USB 2.0	- 3 - 4 (internal)	- 3 - 4 (internal)	- 3 - 4 (internal)
USB 3.2	1	1	1
Expansion Slot	- 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052	- 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052	- 1 x M.2 Key E 2230 - 1 x M.2 Key B 3042/3052
Operating Temp.	-20 °C~60°C	-20°C~60°C	-20°C~60°C
Power Input	DC 12V~24V	DC 12V, incl. AC/DC power adapter	DC 12V~24V
Dimensions W x D x H (mm)	200 x 140 x 37	200 x140 x 37	200 x140 x 37
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	1.5	1.3	1.3
Gross Weight (kg)	2.8	2.5	2.5
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Model	 **NDiS B337**	 **NDiS B338**	 **NDiS B339**
CPU	Intel® Celeron® processor J3455, TDP 10W	Intel® Celeron® processor J6412, TDP 10W	Intel Atom® x7000RE processor series, TDP 6W
Chipset	-	-	-
Graphics	Intel® HD Graphics 500	Intel® UHD Graphics	Intel® UHD Graphics
Memory	1 x DDR3L SO-DIMM, up to 8GB	2 x DDR4 SO-DIMM, up to 32GB	1 x DDR4 SO-DIMM, up to 16GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	-
Flash Storage	M.2 Key M 2242 (SATA 3.0)	1 x M.2 Key M 2280(PCIe 3.0 x4)	1 x M.2 Key M 2242 (PCIe 3.0 x1/SATA 3.0)
Display Output	2 x HDMI® 1.4	3 x HDMI® 2.0	2 x HDMI® 1.4
Max. Display Resolution	3840x2160@30Hz	4096x2160@60Hz	3840x2160@30Hz
Audio I/O	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out - 1 x Mic in - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232	- 1 x RS-232/422/485 - 3 x RS-232	- 1 x RS-232/422/485 - 1 x RS-232
USB 2.0	- 2 - 2 (internal)	5	3 (internal)
USB 3.2	2	1	4
Expansion Slot	1 x Mini PCIe (SIM slot)	- 1 x Mini PCIe (SIM slot) - 1 x M.2 Key B 3042/3052	1 x Mini PCIe (SIM slot)
Operating Temp.	-20°C~60°C	-20°C~60°C	-20°C~60°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V~24V, incl. AC/DC power adapter	DC 12V~24V
Dimensions W x D x H (mm)	200 x 117.6 x 40	200 x 152.6 x 39.8	224 x 150 x 39.8 (w/ mount bracket)
OS Support	Win 11/Win 10/Linux	Win 10	Win 11/Win 10/Linux
Net Weight (kg)	1.3	1.5	1.4
Gross Weight (kg)	2.0	2.0	2.0
Certifications	CE, FCC Class A	CE, FCC Class A, UL	CE, FCC Class A

Duro Edge Computer

Model	NEW  **NDiS B340**	NEW  **NDiS B340-DIF**	 **NDiS B116**
CPU	Intel Atom® x7000RE processor series, TDP 9W	InIntel Atom® x7000RE processor series, TDP 9W	Rockchip RK3399
Chipset	-	-	-
Graphics	Intel® UHD Graphics	Intel® UHD Graphics	Mali-T864 (Embedded)
Memory	1 x DDR5 SO-DIMM, up to 16GB	1 x DDR5 SO-DIMM, up to 16GB	Onboard LPDDR4, 2GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	-
Flash Storage	1 x M.2 Key M 2242 (PCIe 3.0 x1/SATA 3.0)	1 x M.2 Key M 2242 (PCIe 3.0 x1/SATA 3.0)	Onboard eMMC, 8GB
Display Output	2 x HDMI® 2.0	2 x HDMI® 2.0	- 1 x HDMI® 1.4 - 1 x HDMI® 2.0
Max. Display Resolution	4096x2160@60Hz	4096x2160@60Hz	3840x2160/4096x2160 (single display)
Audio I/O	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 2 x RS-232/422/485 - 4 x RS-232(internal)	- 2 x RS-232/422/485 - 4 x RS-232(internal)	1 x RS-232/422/485
USB 2.0	6	6	1
USB 3.2	-	-	1
Expansion Slot	- 1 x M.2 Key B 3042/3052 - 1 x M.2 Key E 2230 - 1 x M.2 Key M 2242	- 1 x M.2 Key B 3042/3052 - 1 x M.2 Key E 2230 - 1 x M.2 Key M 2242 - 1 x PCIe x4 slot	1 x Mini PCIe
Operating Temp.	-20°C~60°C	-20°C~60°C	-20°C~60°C
Power Input	DC 12V~24V	DC 12V~24V	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	132 x 190 x 44	237.2 x 190 x 44	179.5 x 112.5 x 39.5
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Android™ 7.1
Net Weight (kg)	0.7	1.2	0.8
Gross Weight (kg)	1.5	2.0	3.32
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Model	NEW  **NDiS B117**	 **NDiS V1000**	 **NDiS V1100**
CPU	Rockchip RK3568J	AMD Ryzen™ Embedded V1605B, TDP 15W	11th Gen Intel® Core i processor, TDP 15W
Chipset	-	-	-
Graphics	Mali-G52 GPU (Embedded)	AMD Radeon™ Vega 8	- Intel® Iris® Xe Graphics (on i5/i7) - Intel® UHD Graphics (on i3)
Memory	Onboard LPDDR4, 2GB/4GB	2 x DDR4 SO-DIMM, up to 32GB	2 x DDR4 SO-DIMM, up to 64GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	-
Flash Storage	- Onboard eMMC, 32GB/64GB - 1 x microSD slot	1 x M.2 Key M 2242/2280 (SATA 3.0)	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x4)
Display Output	1 x HDMI® 2.0	4 x HDMI® 2.0	4 x HDMI® 2.0
Max. Display Resolution	4096x2160@60Hz	4096x2160@60Hz	4096x2160@60Hz
Audio I/O	- 1 x Line out - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in	- 1 x Line out - 1 x Mic in
COM Port	1 x RS-232/422/485	- 1 x RS-232/422/485 - 3 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232
USB 2.0	-	2 (internal)	1
USB 3.2	2	4	3
Expansion Slot	- 1 x M.2 Key B 3042 (SIM slot) - 1 x M.2 Key E 2230	1 x M.2 Key E 2230	- 1 x Mini PCIe - 1 x M.2 Key B 3042/3052
Operating Temp.	-20°C~60°C	0°C~40°C	0°C~45°C
Power Input	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter	DC 12V, incl. AC/DC power adapter
Dimensions W x D x H (mm)	179.3 x 115.6 x 27.2	190 x 200 x 54.4	190 x165 x 51.1
OS Support	Android™ 13	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	0.3	2.1	2.0
Gross Weight (kg)	5.0	3.29	2.84
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Embedded Touchscreen Computer

Model	 **XPPC 10-100**	 **XPPC 16-101**	 **XPPC 22-100A**
	Indoor		
CPU	Intel® Celeron® processor J3455, TDP 10W	Intel® Celeron® processor J3455, TDP 10W	Intel® Celeron® processor J3455, TDP 10W
LCD Size	10.1", 16:10	15.6", 16:9	21.5", 16:9
Max. Resolution	1280x800 WXGA	1920x1080 FHD	1920x1080 FHD
Touchscreen	10-point PCAP	10-point PCAP	10-point PCAP
Surface Treatment	AF	AF	AF
Touch Light Transmission	90%	90%	85%
Luminace (cd/m2)	- Panel: 400 - XPPC touch: 90% of panel's luminance after optical bonding	- Panel: 450 - XPPC touch: 90% of panel's luminance after optical bonding	- Panel: 400 - XPPC touch: 85% of panel's luminance after air bonding
Contrast Ratio	800:1	1000:1	1000:1
LCD Color	16.7M	16.7M	16.7M
Viewing Angle	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED	LED
Memory	1 x DDR3L SO-DIMM, up to 8GB	1 x DDR3L SO-DIMM, up to 8GB	1 x DDR3L SO-DIMM, up to 8GB
Storage	1 x M.2 Key M 2242 (SATA 3.0)	1 x M.2 Key M 2242 (SATA 3.0)	1 x M.2 Key M 2242 (SATA3.0)
2nd Display	1 x HDMI® 2.0	1 x HDMI® 1.4	1 x HDMI® 2.0
Gigabit LAN	2	2	2
USB 3.2	2	2	2
USB 2.0	-	2	-
COM Port	1 x RS-232/422/485	1 x RS-232/422/485	1 x RS-232/422/485
Audio I/O	1 x Line out	1 x Line out	1 x Line out
Expansion Slot	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)	1 x Mini PCIe (SIM slot)
Housing Material	Metal	Metal	Metal
Mounting	- VESA 75mm x 75mm - Panel mount (optional kit) - Open frame (optional kit)	- VESA 100mm x 100mm - Panel mount (optional kit) - Open frame (optional kit)	- VESA 100mm x 100mm - Panel mount (optional kit) - Open frame (optional kit)
Power Input	DC 12V	DC 19V	DC 19V
Power Adapter	60W AC/DC power adapter w/ lock type	90W AC/DC power adapter w/ lock type	90W AC/DC power adapter w/ lock type
Operating Temp.	0°C~50°C	0°C~50°C	0°C~50°C
Storage Temp.	-20°C~80°C	-20°C~80°C	-20°C~80°C
Operating Humidity	10%~90% (non-condensing)	10%~90% (non-condensing)	10%~90% (non-condensing)
IP Level	IP65 on the front	IP65 on the front	IP65 on the front
Cut-Out Size (W x H) (mm)	246.5 x 164.5 (horizontal)	370.5 x 240 (horizontal)	508.4 x 303.4 (horizontal)
Dimensions (W x H x D) (mm)	260.3 x 178.3 x 44.7 (horizontal)	382.2 x 251.4 x 51.9 (horizontal)	520.6 x 315.6 x 54 (Horizontal)
OS Support	Win 10/Linux	Win 10/Linux	Win 10/Linux
Net Weight (kg)	2.0	3.0	5.0
Gross Weight (kg)	3.0	4.7	7.5
Certifications	CE, FCC Class A, UL	CE, FCC Class A	CE, FCC Class A

Model	 **XPPC 10-10N97**	 **XPPC 16-10N97**	NEW  **XPPC 24-10N97A**
	Indoor		
CPU	Intel® processor N97, TDP 12W	Intel® processor N97, TDP 12W	Intel® processor N97, TDP 12W
LCD Size	10.1", 16:10	15.6", 16:9	23.8", 16:9
Max. Resolution	1280x800 WXGA	1920x1080 FHD	1920x1080 FHD
Touchscreen	10-point PCAP	10-point PCAP	10-point PCAP
Surface Treatment	AF	AF	AF
Touch Light Transmission	90%	90%	85%
Luminace (cd/m2)	- Panel: 400 - XPPC touch: 90% of panel's luminance after optical bonding	- Panel: 450 - XPPC touch: 90% of panel's luminance after optical bonding	- Panel: 350 - XPPC touch: 85% of panel's luminance after air bonding
Contrast Ratio	800:1	1000:1	1000:1
LCD Color	16.7M	16.7M	16.7M
Viewing Angle	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89(U), 89(D), 89(L), 89(R)
Backlight	LED	LED	LED
Memory	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB
Storage	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)
2nd Display	1 x HDMI® 1.4	1 x HDMI® 1.4	1 x HDMI® 1.4
Gigabit LAN	2	2	2
USB 3.2	2	2	2
USB 2.0	2	2	2
COM Port	1 x RS-232/422/485	1 x RS-232/422/485	1 x RS-232/422/485
Audio I/O	1 x Speaker out	1 x Line out	1 x Line out
Expansion Slot	1 x Mini PCIe	1 x Mini PCIe	1 x Mini PCIe
Housing Material	Metal	Metal	Metal
Mounting	- VESA 75mm x 75mm - Panel mount (optional kit) - Open frame (optional kit)	- VESA 100mm x 100mm - Panel mount (optional kit) - Open frame (optional kit)	- VESA 100mm x 100mm - Panel mount (optional kit) - Open frame (optional kit)
Power Input	DC 12V	DC 12V	DC 12V
Power Adapter	60W AC/DC power adapter with lock type	65W AC/DC power adapter with lock type	96W AC/DC power adapter with lock type
Operating Temp.	0°C~50°C	0°C~50°C	0°C~50°C
Storage Temp.	-20°C~80°C	-20°C~80°C	-20°C~80°C
Operating Humidity	10%~90% (non-condensing)	10%~90% (non-condensing)	10%~90% (non-condensing)
IP Level	IP65 on the front	IP65 on the front	IP65 on the front
Cut-Out Size (W x H) (mm)	246.5 x 164.5 (horizontal)	370.5 x 240 (horizontal)	546.7 x 326.1 (horizontal)
Dimensions (W x H x D) (mm)	260.3 x 178.3 x 47.9 (horizontal)	382.2 x 251.4 x 51.8 (horizontal)	557 x 336.7 x 55 (horizontal)
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 10/Linux
Net Weight (kg)	1.62	2.84	6.0
Gross Weight (kg)	3.0	4.6	8.5
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Embedded Touchscreen Computer

Model	 **XPPC 24-100A**	NEW  **SPPC 16-10N150**	 **XPPC 10-200**
	Indoor		
CPU	Intel® Celeron® processor J3455, TDP 10W	Intel® processor N150, PBP 6W	Intel® Core™ i5-1145G7E/ i3-1115G4E processor, TDP 15W
LCD Size	23.8", 16:9	15.6", 16:9	10.1", 16:10
Max. Resolution	1920x1080 FHD	1920x1080 FHD	1280x800 WXGA
Touchscreen	10-point PCAP	10-point PCAP	10-point PCAP
Surface Treatment	AF	AF	AF
Touch Light Transmission	85%	90%	90%
Luminace (cd/m2)	- Panel: 350 - XPPC Touch: 85% of panel's luminance after air bonding	- Panel : 450 - XPPC Touch : 90% of panel's luminance after optical bonding	- Panel: 400 - XPPC Touch: 90% of panel's luminance after optical bonding
Contrast Ratio	1000:1	1000:1	800:1
LCD Color	16.7M	16.7M	16.7M
Viewing Angle	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED	LED
Memory	1 x DDR3L SO-DIMM, up to 8GB	1 x DDR5 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 32GB
Storage	1 x M.2 Key M 2242 (SATA 3.0)	1 x M.2 Key M 2280 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2280 (PCIe 3.0 x4)
2nd Display	1 x HDMI® 2.0	2 x USB Type C	1 x HDMI® 2.0
Gigabit LAN	2	2	2
USB 3.2	2	2 x USB Type C, 1 x USB Type A	4
USB 2.0	-	-	-
Power Delivery	-	PD 3.0 (USB Type C)	-
COM Port	1 x RS-232/422/485	1 x RS-232/422/485, 1 x RS-232	1 x RS-232/422/485
Audio I/O	1 x Line out	1 x Line out	1 x Line out
Expansion Slot	1 x Mini PCIe (SIM slot)	- 1 x M.2 Key E 2230 - 1 x M.2 Key B 3052/3042/2242	1 x M.2 Key E 2230
Housing Material	Metal	Metal	Metal
Mounting	- VESA 100mm x100mm - Panel mount (optional kit) - Open frame (optional kit)	VESA 100mm x100mm	- VESA 75mm x 75mm - Panel mount (optional kit) - Open frame (optional kit)
Power Input	DC 19V	DC 28V (USB Type C)	DC 12V
Power Adapter	90W AC/DC power adapter w/ lock type	140W AC/DC Type-C power adapter w/o lock type	60W AC/DC power adapter w/ lock type
Operating Temp.	0°C~50°C	0°C~50°C	0°C~50°C
Storage Temp.	-20°C~80°C	-20°C~60°C	-20°C~80°C
Operating Humidity	10%~90% (non-condensing)	10%~90% (non-condensing)	10%~90% (non-condensing)
IP Level	IP65 on the front	IP65 on the front	IP65 on the front
Cut-Out Size (W x H) (mm)	546.7 x 326.1 (horizontal)	370.5 x 240 (horizontal)	246.5 x 164.5 (horizontal)
Dimensions (W x H x D) (mm)	557 x 336.7 x 55 (horizontal)	384.9 x 234. x 20 (horizontal)	260.3 x 178.3 x 50.4 (horizontal)
OS Support	Win 10/Linux	Win 10/ Win 11/ Linux	Win 10/Linux
Net Weight (kg)	6.0	2.3	2.0
Gross Weight (kg)	8.5	3.0	3.0
Certifications	CE, FCC Class A	CE, FCC Class B	CE, FCC Class A

Model	 **XPPC 16-200**	 **XPPC 24-200A**	NEW  **XPPC 16-201**
	Indoor		
CPU	Intel® Core™ i5-1145G7E/ i3-1115G4E processor, TDP 15W	Intel® Core™ i5-1145G7E/ i3-1115G4E processor, TDP 15W	Intel® Core™ Ultra processor (Series 1), PBP 15W
LCD Size	15.6", 16:9	23.8", 16:9	15.6", 16:9
Max. Resolution	1920x1080 FHD	1920x1080 FHD	1920x1080 FHD
Touchscreen	10-point PCAP	10-point PCAP	10-point PCAP
Surface Treatment	AF	AF	AF
Touch Light Transmission	90%	85%	90%
Luminace (cd/m2)	- Panel: 450 - XPPC Touch: 90% of panel's luminance after optical bonding	- Panel: 350 - XPPC Touch: 85% of panel's luminance after air bonding	- Panel : 450 - XPPC Touch : 90% of panel's luminance after optical bonding
Contrast Ratio	1000:1	1000:1	1000:1
LCD Color	16.7M	16.7M	16.7M
Viewing Angle	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED	LED
Memory	1 x DDR4 SO-DIMM, up to 32GB	1 x DDR4 SO-DIMM, up to 32GB	2 x DDR5 SO-DIMM, up to 96GB
Storage	1 x M.2 Key M 2280 (PCIe 3.0 x4)	1 x M.2 Key M 2280 (PCIe 3.0 x4)	- 1 x1 x M.2 Key E 2230 - 1 x M.2 Key M 2280 (PCIe 3.0 x4/SATA 3.0)
2nd Display	- 1 x HDMI® 2.0 - 1 x DP++	- 1 x HDMI® 2.0 - 1 x DP++	2 x HDMI® 2.0
Gigabit LAN	2	2	2
USB 3.2	4	4	1
USB 2.0	-	-	3
Power Delivery	-	-	-
COM Port	1 x RS-232/422/485	1 x RS-232/422/485	1 x RS-232/422/485
Audio I/O	1 x Line out	1 x Line out	1 x Line out
Expansion Slot	1 x M.2 Key E 2230	1 x M.2 Key E 2230	1 x M.2 Key E 2230
Housing Material	Metal	Metal	Metal
Mounting	- VESA 100mm x100mm - Panel mount (optional kit) - Open frame (optional kit)	- VESA 100mm x100mm - Panel mount (optional kit) - Open frame (optional kit)	- VESA 100mm x100mm - Panel mount (optional kit) - Open frame (optional kit)
Power Input	DC 12V	DC 12V	DC 12V
Power Adapter	96W AC/DC power adapter w/ lock type	96W AC/DC power adapter w/ lock type	96W AC/DC power adapter w/ lock type
Operating Temp.	0°C~50°C	0°C~50°C	0°C~50°C
Storage Temp.	-20°C~80°C	-20°C~80°C	-20°C~80°C
Operating Humidity	10%~90% (non-condensing)	10%~90% (non-condensing)	10%~90% (non-condensing)
IP Level	IP65 on the front	IP65 on the front	IP65 on the front
Cut-Out Size (W x H) (mm)	370.5 x 240 (horizontal)	557 x 326.1 (horizontal)	370.5 x 240 (horizontal)
Dimensions (W x H x D) (mm)	382.2 x 251.4 x 51.9 (horizontal)	557 x 336.7 x 55 (horizontal)	382.2 x 251.4 x 51.9 (horizontal)
OS Support	Win 10/Linux	Win 10/Linux	Win 10/Win 11/Linux
Net Weight (kg)	3.0	5.8	2.84
Gross Weight (kg)	4.7	7.85	4.5
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Embedded Touchscreen Computer

Model	 NEW **HPPC 15-10X7211**	 NEW **HPPC 12-10X7211**
	Semi-Outdoor	
CPU	Intel Atom® x7211RE processor, TDP 6W	Intel Atom® x7211RE processor, TDP 6W
LCD Size	15", 4:3	12.1", 4:3
Max. Resolution	1024 x768 XGA	1024 x768 XGA
Touchscreen	Waterproof 10-point PCAP	Waterproof 10-point PCAP
Surface Treatment	- AF + AG - Anti-IR & UV	- AF + AG - Anti-IR & UV
Touch Light Transmission	80%	80%
Luminace (cd/m2)	- Panel: 1800 - HPPC touch: 80% of panel's luminance after optical bonding	- Panel: 1300 - HPPC touch: 80% of panel's luminance after optical bonding
Contrast Ratio	2500:1	1000:1
LCD Color	16.7M	16.7M
Viewing Angle	88 (U), 88 (D), 88 (L), 88 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED
Memory	1 x DDR4 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 16GB
Storage	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)
2nd Display	1 x HDMI® 1.4	1 x HDMI® 1.4
Gigabit LAN	2	2
USB 3.2	2	2
USB 2.0	2	2
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)
Audio I/O	1 x Line out	1 x Line out
Expansion Slot	1 x Mini PCIe	1 x Mini PCIe
Housing Material	Metal	Metal
Mounting	- VESA 100mm x 100mm - Panel mount (optional kit) - Open frame (optional kit)	- VESA 100mm x 100mm - Panel mount (optional kit) - Open frame (optional kit)
Power Input	DC 12V~24V	DC 12V~24V
Power Adapter	-	-
Operating Temp.	-20°C~60°C	-20°C~60°C
Storage Temp.	-20°C~80°C	-20°C~80°C
Operating Humidity	10%~90% (non-condensing)	10%~90% (non-condensing)
IP Level	IP65 on the front	IP65 on the front
Cut-Out Size (W x H) (mm)	341.6 x 284.35 (horizontal)	281.9 x 235.8 (horizontal)
Dimensions (W x H x D) (mm)	351.9 x 295.75 x 58.15 (horizontal)	293.56 x 245.46 x 56.65 (horizontal)
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	4.2	3.08
Gross Weight (kg)	5.8	4.01
Certifications	CE, FCC Class A	CE, FCC Class A

Embedded Touchscreen Monitor

Model	 NEW **XPPD 16-C01**	 NEW **XPPD 24-01**
	Indoor	
LCD Size	15.6", 16:9	23.8", 16:9
Max. Resolution	1920x1080 FHD	1920x1080 FHD
Touch Screen	10-point PCAP	10-point PCAP
Surface Treatment	AF	AF
Touch Light Transmission	90%	85%
Luminace (cd/m2)	- Panel: 450 - XPPC Touch: 90% of panel's luminance after optical bonding	- Panel: 350 - XPPC Touch: 85% of panel's luminance after air bonding
Contrast Ratio	1000:1	1000:1
LCD Color	16.7M	16.7M
Viewing Angle	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED
Input	- 1 x USB, Type C - 1 x USB 2.0, Type B for touch - 1 x HDMI® - 1 x DP - 1 x Audio speaker out (optional)	- 1 x HDMI® - 1 x USB 2.0, Type-A for touch - 1 x Audio speaker out (optional)
Housing Material	Metal	Metal
Mounting	VESA 100mm x 100mm	VESA 100mm x 100mm
Power Delivery	PD 2.0	-
Power Input	DC 12V	DC 12V
Power Adapter	50W AC/DC power adapter with lock type	60W AC/DC power adapter with lock type
Operating Temp.	0°C~50°C	0°C~50°C
Storage Temp.	-20°C~80°C	-20°C~80°C
Operating Humidity	10%~90% (non-condensing)	10%~90% (non-condensing)
IP level	IP65 on the front	IP65 on the front
Cut-Out Size (W x H) (mm)	370.5 x 240 (horizontal)	546.7 x 326.1 (horizontal)
Dimensions (W x H x D) (mm)	382.2 x 251.4 x 40.2 (horizontal)	557 x 336.7 x 42.5 (horizontal)
OS Support	Win 10/Linux	Win 10/Linux
Net Weight (kg)	2.84	5.8
Gross Weight (kg)	4.5	7.85
Certifications	CE, FCC Class A	CE, FCC Class A

Embedded Computing Board

Model	 X100	 X101	 X102
Type	3.5"	3.5"	3.5"
CPU	- Intel® Celeron® Processor N3350, TDP 6W - Intel® Celeron® Processor J3455, TDP 10W	Intel® Celeron® Processor J3455, TDP 10W	- Intel® processor N50, TDP 6W - Intel® processor N97, TDP 12W - Intel® Core™ i3-N305 processor, TDP 15W
Chipset	-	-	-
Graphics	Intel® HD Graphics 500	Intel® HD Graphics 500	Intel® UHD Graphics
Memory	1 x DDR3L SO-DIMM, up to 8GB	1 x DDR3L SO-DIMM, up to 8GB	1 x DDR4 SO-DIMM, up to 16GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	1 x SATA 3.0
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0)	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)
Display Output	- 1 x HDMI® 2.0 - 1 x LVDS (internal)	- 2 x HDMI® 1.4b - 1 x eDP (option: LVDS, internal)	- 2 x HDMI® 2.0 - 1 x eDP (option: LVDS, internal)
Max. Display Resolution	3840x2160@60Hz	3840x2160@30Hz	3840x2160@30Hz
Audio I/O	1 x Line out (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 (Internal) - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)
USB 2.0	4 (internal)	- 2 - 2 (internal)	2 (internal)
USB 3.2	2	2	4
Expansion Slot	1 x Mini PCIe (PCIe 2.0/USB 2.0/SATA 3.0)	1 x Mini PCIe (PCIe 2.0/USB 2.0/SATA 3.0)	1 x Mini PCIe (PCIe 3.0/USB 2.0)
SIM Slot	Yes	Yes	Yes
Operating Temp.	0°C~60°C	0°C~60°C	-20°C~80°C
Power Input	DC 12V/19V	DC 12V/19V	DC 12V
Dimensions W x H (mm)	146 x 102	146 x 102	146 x 102
OS Support	Win 10/Linux	Win 10/Linux	Win 10/Win 11/Linux
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Model	NEW  X1025	 X103	NEW  X104
Type	3.5"	3.5"	3.5"
CPU	- Intel® processor N50, TDP 6W - Intel® processor N97, TDP 12W - Intel® Core™ i3-N305 processor, TDP 15W	- Intel Atom® x6211E processor, TDP 6W - Intel Atom® x6413E processor, TDP 9W	- Intel® processor N150, PBP 6W - Intel® Core™ 3 processor N355, PBP 15W
Chipset	-	-	-
Graphics	Intel® UHD Graphics	Intel® UHD Graphics	Intel® UHD Graphics
Memory	1 x DDR5 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 32GB	1 x DDR4 SO-DIMM, up to 16GB
Gigabit LAN	2	3	2
WLAN	Option	Option	Option
Hard Disk Interface	1 x SATA 3.0	-	1 x SATA 3.0
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key B 3052 (SATA 3.0/USB 2.0/USB 3.0)	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)
Display Output	- 2 x HDMI® 2.0 - 1 x eDP (option: LVDS, internal)	- 1 x HDMI® 1.4 - 1 x LVDS (internal)	- 2 x HDMI® 2.0 - 1 x eDP (option: LVDS, internal)
Max. Display Resolution	3840x2160@30Hz	3840x2160@30Hz	3840x2160@30Hz
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 2 x RS-232/422/485 - 4 x RS-232 (internal)	- 1 x RS-232/422/485 - 1 x RS-232 (internal)
USB 2.0	2 (internal)	4 (internal)	2 (Internal)
USB 3.2	4	4	4
Expansion Slot	1 x Mini PCIe (PCIe 3.0/USB 2.0)	- 1 x Mini PCIe (PCIe or SATA 3.0/USB 2.0) - 1 x M.2 Key E 2230	1 x Mini PCIe (PCIe 3.0/USB 2.0)
SIM Slot	Yes	Yes	Yes
Operating Temp.	-20°C~80°C	-40°C~85°C	-20°C~80°C
Power Input	DC 12V	DC 12V~24V	DC 12V
Dimensions W x H (mm)	146 x 102	146 x 102	146 x 102
OS Support	Win 10/Win 11/Linux	Win 10/Win 11/Linux	Win 10/Win 11/Linux
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Embedded Computing Board

Model	NEW  **X1045**	 **X200**	 **X201**
Type	3.5"	3.5"	3.5"
CPU	- Intel® processor N150, PBP 6W - Intel® Core™ 3 processor N355, PBP 15W	11th Gen Intel® Core™ i processor, TDP 15W	Intel® Core™ Ultra processor (Series 1), PBP 15W
Chipset	-	-	-
Graphics	Intel® UHD Graphics	Intel® UHD Graphics on i3, Intel® Iris® Xe Graphics on i5	Intel® Graphics
Memory	1 x DDR5 SO-DIMM, up to 16GB	1 x DDR4 SO-DIMM, up to 32GB	2 x DDR5 SO-DIMM, up to 96GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	1 x SATA 3.0	1 x SATA 3.0 (share with M.2 Key M)	-
Flash Storage	1 x M.2 Key M 2242 (SATA 3.0/PCIe 3.0 x1)	1 x M.2 Key M 2280 (PCIe 3.0 x4/SATA 3.0)	1 x M.2 Key M 2280 (PCIe 3.0 x4, SATA 3.0)
Display Output	- 2 x HDMI® 2.0 - 1 x eDP (option: LVDS, internal)	- 1 x DP++ - 1 x HDMI® 2.0a - 1 x eDP (internal)	- 2 x HDMI® 2.0 - 1 x LVDS/eDP (internal)
Max. Display Resolution	3840x2160@30Hz	4096x2304@60Hz	4096x2160@60Hz
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)
COM Port	- 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 (internal) - 1 x RS-232 (internal)	- 2 x RS-232/422/485 - 4 x RS-232 (internal)
USB 2.0	2 (Internal)	4 (internal)	- 3 - 4 (internal)
USB 3.2	4	4	1
Expansion Slot	1 x Mini PCIe (PCIe 3.0/USB 2.0)	1 x M.2 Key E 2230 (PCIe 3.0/USB 2.0)	- 1 x M.2 Key E 2230 (PCIe 3.0 x1/USB 2.0) - 1 x M.2 Key M 2280 (PCIe x1/SATA 3.0) - 1 x M.2 Key B 3052/2242 (PCIe 4.0 x1/ USB 3.0/USB 2.0)
SIM Slot	Yes	-	Yes
Operating Temp.	-20°C~80°C	-20°C~60°C	-20°C~80°C
Power Input	DC 12V	DC 12V	DC 12V
Dimensions W x H (mm)	146 x 102	146 x 102	146 x 102
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Model	NEW  **X202**	NEW  **X203**	 **X300**
Type	3.5"	3.5"	Mini-ITX
CPU	13th Gen Intel® Core™ i processor, PBP 15W	Intel® Core™ Ultra 7/5 processor (Series 2), PBP 15W	8th Gen Intel® Core™ i processor, TDP 35W
Chipset	-	-	Intel® PCH Q370/H310
Graphics	- Intel® Iris® Xe LPG Graphics (on i7, i5) - Intel® UHD Graphics (on i3)	Intel® Graphics	Intel® UHD Graphics 630
Memory	2 x DDR5 SO-DIMM, up to 96GB	2 x DDR5 SO-DIMM, up to 96GB	2 x DDR4 SO-DIMM, up to 32GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	-	-	1 x SATA 3.0 (Q370)
Flash Storage	1 x M.2 Key M 2280 (PCIe 3.0 x4, SATA 3.0)	1 x M.2 Key M 2280 (PCIe 3.0 x4, SATA 3.0)	1 x M.2 Key M 2280 (Q370: SATA 3.0/PCIe x4, H310: SATA 3.0)
Display Output	- 2 x HDMI® 2.0 - 1 x LVDS/eDP (internal)	- 2 x HDMI® 2.0 - 1 x LVDS/eDP (internal)	- Q370: 3 x HDMI® 2.0 - H310: 2 x HDMI® 2.0 + 1x LVDS (internal)
Max. Display Resolution	4096x2160@60Hz	4096x2160@60Hz	4096x2160@60Hz
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal)
COM Port	- 2 x RS-232/422/485 (internal) - 2 x RS-232 (internal)	- 2 x RS-232/422/485 (internal) - 4 x RS-232 (internal)	- 1 x RS-232/422/485 (internal) - 2 x RS-232 (internal)
USB 2.0	- 3 - 4 (internal)	- 3 - 4 (internal)	- 6 (Q370, internal) - 4 (H310, internal)
USB 3.2	1	1	4
Expansion Slot	- 1 x M.2 Key E 2230 (PCIe 3.0/USB 2.0) - 1 x M.2 Key M 2280 (PCIe 4.0 x4/SATA 3.0) - 1 x M.2 Key B 3042/3052 (PCIe 4.0 x1/ USB 3.0/USB 2.0)	- 1 x M.2 Key E 2230 (PCIe 3.0 x1/ USB 2.0) - 1 x M.2 Key M 2280 (PCIe x1/ SATA 3.0) - 1 x M.2 Key B 3042/3052 (PCIe 4.0 x1/USB 3.0/USB 2.0)	- 1 x M.2 Key E 2230 (PCIe 3.0 x1/USB 2.0) - 1 x PCIe x16
SIM Slot	Yes	Yes	-
Operating Temp.	-20°C~80°C	-20°C~80°C	0°C~60°C
Power Input	DC 12V	DC 12V	DC 12V
Dimensions W x H (mm)	146 x 102	146 x 102	170 x170
OS Support	Win 11/Win 10/Linux	Win 11/Win 10/Linux	Win 10/Linux
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Embedded Computing Board

Model	 **X302**	NEW  **X304-MTX**	 **V1000**
Type	Mini-ITX	Mini-ITX	Mini-ITX
CPU	9/8th Gen Intel® Core™ i processor, TDP 35W	14/13/12th Gen Intel® Core™ i processor/ Intel® Core™ processor (Series 2), PBP 35W	AMD Ryzen™ Embedded V1605B, TDP 15W
Chipset	Intel® PCH Q370/H310	Intel® PCH Q670E/H610E	-
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 770	AMD Radeon™ Vega 8
Memory	2 x DDR4 SO-DIMM, up to 32GB	2 x DDR5 SO-DIMM, up to 64GB	2 x DDR4 SO-DIMM, up to 32GB
Gigabit LAN	2	2	2
WLAN	Option	Option	Option
Hard Disk Interface	2 x SATA 3.0	1 x SATA 3.0	-
Flash Storage	1 x M.2 Key B 2242 (Q370: PCIe 3.0 x1/ SATA 3.0, H310: SATA 3.0)	1 x M.2 Key M 2280 (PCIe 3.0 x4/SATA 3.0)	1 x M.2 Key M 2242/2280 (SATA 3.0/PCIe x1)
Display Output	- 1 x VGA - 1 x HDMI® 1.4 - 1 x LVDS (internal)	- 3 x HDMI® 2.0 - 1x LVDS (option: eDP, internal)	4 x HDMI® 2.0
Max. Display Resolution	4096x2160@30Hz	4096x2160@60Hz	4096x2160@60Hz
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal) - 1 x Speaker (internal)	- 1 x Line out (internal) - 1 x Mic in (internal)
COM Port	- 3 x RS-232/422/485 - 3 x RS-232 (internal)	- 1x RS-232/422/485 (internal) - 3 x RS-232 (internal)	- 1x RS-232/422/485 (internal) - 3 x RS-232 (internal)
USB 2.0	- 6 (Q370, internal) - 4 (H310, internal)	- 4 (Q370, internal) - 5 (H310, internal)	2 (internal)
USB 3.2	4	- 4 (Q670E) - 3 (H610E)	4
Expansion Slot	- 1 x PCIe x16 - 1 x M.2 Key E 2230 (PCIe 3.0 x1/USB 2.0) - 1 x M.2 Key B 3042 (Q370: PCIe 3.0 x1/ SATA 3.0, H310: SATA 3.0)	- 1 x M.2 Key E 2230 (PCIe 3.0 x2/USB 2.0) - 1 x 1 x M.2 Key B 3052 (PCIe 3.0 x1/USB 3.0/USB 2.0)	- 1 x M.2 Key E 2230 (PCIe 3.0/USB 2.0) - 1 x PCIe x8
SIM Slot	Yes	Yes	-
Operating Temp.	0°C~60°C	0°C~70°C	0°C~60°C
Power Input	DC 12V	DC 12V	DC 12V
Dimensions W x H (mm)	170 x 170	170 x 170	170 x 170
OS Support	Win 10/Linux	Win 11/Win 10/Linux	Win 10/Linux
Certifications	Compliant with CE, FCC Class A	Compliant with CE, FCC Class A	Compliant with CE, FCC Class A

Embedded Computing Board

Model	 **V1100**
Type	EPIC
CPU	- Intel® Core i7-1185G7E processor, TDP 15W - Intel® Core i5-1145G7E processor, TDP 15W - Intel® Core i3-1115G4E processor, TDP 15W
Chipset	-
Graphics	Intel® Iris® X^{e}
Memory	2 x DDR4 SO-DIMM, up to 64GB
Gigabit LAN	2
WLAN	Option
Hard Disk Interface	-
Flash Storage	1 x M.2 Key M 2280 (SATA 3.0/PCIe 4.0 x4)
Display Output	4 x HDMI® 2.0
Max. Display Resolution	4096x2160@60Hz
Audio I/O	- 1 x Line out (internal) - 1 x Mic in (internal)
COM Port	- 1 x RS-232/422/485 (internal) - 3 x RS-232 (internal)
USB 2.0	- 1 - 4 (internal)
USB 3.2	3
Expansion Slot	- 1 x Mini PCIe (PCIe 3.0/USB 2.0) - 1 x M.2 Key B 3052 (PCIe 3.0/USB 3.0)
SIM Slot	Yes
Operating Temp.	0°C~60°C
Power Input	DC 12V
Dimensions W x H (mm)	165 x 123
OS Support	Win 11/Win 10/Linux
Certifications	Compliant with CE, FCC Class A

Expansion Module

Model	NEW  **NTK-USB-2COM**
Type	Customize
Gigabit LAN	-
COM Port	2 x RS-232/422/485
Operating Temp.	-20°C~85°C
Power Input	USB, 5V
Dimensions (mm)	20 x 80
OS Support	Win 11/Win 10/Linux
Certifications	CE, FCC Class A

Model	NEW  **NTK-MEE-LAN** **NTK-IO-RJ45**	NEW  **NTK-MNE-8COM** **NTK-IO-2COM**
Type	M.2 Key E 2230	Mini PCIe
Gigabit LAN	1	-
COM Port	-	8 x RS-232
Operating Temp.	-20°C~85°C	-20°C~85°C
Power Input	-	-
Dimensions (mm)	- Module: 22 x 30 - IO: 32 x 36	- Module: 30 x 50.95 - IO: 20 x 80
OS Support	Win11/Win 10/ Linux	Win11/Win 10/ Linux
Certifications	CE, FCC Class A	CE, FCC Class A

Edge AI Computer

Model	 **AIEdge-X®300-RTX30**	 **AIEdge-X®500**	NEW  **AIEdge-X®80-NX-S**
CPU	9/8th Gen Intel® Core™ i processor, TDP 65W	9/8th Gen Intel® Core™ i processor, TDP 95W	NVIDIA® Jetson Orin™ NX, up to 117/157 TOPS in Super Mode
Chipset	Intel® PCH Q370	Intel® PCH Q370	-
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 630	1024-core NVIDIA® Ampere GPU w/ 32 Tensor Cores
Memory	DDR4 SO-DIMM, up to 32GB	DDR4 SO-DIMM, up to 32GB	8GB/16GB
Gigabit LAN	2	2	4
WLAN	Option	-	-
Hard Disk Interface	1 x SATA 3.0	4 x SATA 3.0 (hot-swap)	-
Flash Storage	- 1 x M.2 Key M 2280 (SATA 3.0/ PCIe 3.0 x4) - 1 x 2.5" SSD bay	- 1 x M.2 Key M 2280 (SATA 3.0/ PCIe 3.0 x4) - 4 x 2.5" SSD bay	1 x M.2 Key M 2280 (PCIe 3.0 x4)
Display Output	3 x HDMI® 2.0	1 x HDMI® 2.0	1 x HDMI® 2.0
Max. Display Resolution	4096x2160@60Hz	4096x2160@60Hz	3840x2160@60Hz
Audio I/O	1 x Line out	1 x Line out	-
COM Port	- 1 x RS-232 - 1 x RS-232/422/485 - 1 x RS-232 (internal)	- 1 x RS-232/422/485 - 3 x RS-232 (internal)	- 1 x RS-232/422/485 - 3 x RS-232 (only Tx/Rx)
USB 2.0	4 (internal)	- 1 - 6 (internal)	2 (Type-A)
USB 3.2	4	2	2
Expansion Slot	- 1 x M.2 Key E 2230 - 1 x PCIe 3.0 x16, two slot space	- 1 x PCIe3.0 x16, two slot space - 1 x PCIe 3.0 x4 - 1 x PCIe	- 1 x Mini PCIe - 1 x M.2 Key B 2280
Add-on Card Length (mm)	Up to 290mm	Up to 327mm	-
Operating Temp.	0°C~45°C	0°C~45°C	-20°C~60°C
Power Supply	850W ATX	850W ATX	150W
Dimensions W x D x H (mm)	360 x 335 x 85	290 x 360 x 150	210 x 154 x 50
OS Support	Win 10/Linux	Win 10/Linux	JetPack™ 6.2
Net Weight (kg)	4.9	7.6	2.03
Gross Weight (kg)	5.8	9.5	2.42
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

Model	NEW  **AIEdge-X®80-NA**	NEW  **AIEdge-X®310**	Coming soon  **AIEdge-X®510**
CPU	NVIDIA® Jetson Orin Nano™, up to 34/67 TOPS	14/13/12th Gen Intel® Core™ i processor, PBP 65W	Intel® Xeon Granite Rapids-W Processor, PBP 350W
Chipset	-	Intel® PCH H610E	Intel® PCH W890
Graphics	512/1024-core NVIDIA® Ampere GPU w/ 16/32 Tensor Cores	Intel® UHD Graphics 770	Intel® UHD Graphics 770
Memory	4GB/8GB	DDR5 SO-DIMM, up to 64GB	DDR5 SO-DIMM, up to 1TB
Gigabit LAN	4	2	4
WLAN	-	-	-
Hard Disk Interface	-	2 x SATA 3.0	8 x SATA 3.0
Flash Storage	1 x M.2 Key M 2280 (PCIe 3.0 x4)	- 1 x M.2 Key M 2242 (SATA 3.0/ PCIe 3.0 x4) - 2 x 2.5" SSD bay	- 2 x M.2 Key M 2280 (PCIe 3.0 x4) - 8 x 2.5" SSD bay or 4 x 3.5" HDD bay
Display Output	1 x HDMI® 2.0	2 x DP 1.2	1 x HDMI® 1.4
Max. Display Resolution	3840x2160@60Hz	4096x2160@60Hz	1920x1080@30Hz
Audio I/O	-	- 1 x Line out - 1 x Mic in	- 1 x Line out - 1 x Mic in
COM Port	- 1 x RS-232/422/485 - 3 x RS-232 (only Tx/Rx)	- 1 x RS-232 - 1 x RS-232/422/485	2 x RS-232/422/485
USB 2.0	2 (Type-A)	- 2 - 2 (internal)	- 2 - 2 (internal)
USB 3.2	2	4	6
Expansion Slot	- 1 x Mini PCIe - 1 x M.2 Key B 2280	1 x PCIe 4.0 x16, three slot space	- 4 x PCIe 5.0 x16, 1 x PCIe x8 - 1 x M.2 Key B, 1 x M.2 Key E
Add-on Card Length (mm)	-	Up to 340 (L) × 141 (W) × 70 (H)	Up to 340 (L) × 141 (W) × 70 (H)
Operating Temp.	-20°C~60°C	0°C~45°C	0°C~45°C
Power Supply	150W	850W ATX	3200W Redundant
Dimensions W x D x H (mm)	210 x 154 x 50	380 x 390 x 98.5	515 x 430 x 176
OS Support	JetPack™ 6.2	Win 11/Win 10/Linux	Win 11/Win 10/Linux
Net Weight (kg)	2.03	6.7	12.0
Gross Weight (kg)	2.42	8.0	13.5
Certifications	CE, FCC Class A	CE, FCC Class A	CE, FCC Class A

About NEXCOM

Reliable Partner for the AIoT Digital Transformation Solutions

Committed to Customer Success

Founded in 1992 and headquartered in Taipei, Taiwan, NEXCOM is committed to being a trustworthy partner in building the AIoT digital transformation solutions. To surpass customers' expectations, NEXCOM sets itself apart by leveraging its decades of experience in industrial computing, a highly talented R&D team, and exceptional customer service. With these core strengths, NEXCOM has enabled its customers to win key projects in a diverse range of industries.

With its focus on delivering these core values to better serve customers, NEXCOM integrates its capabilities and operates six global businesses: IoT Automation Solutions (IAS), Intelligent Video Surveillance (IDS), Intelligent Platform @ Smart City (IPS), Mobile Computing Solutions (MCS), Medical & Healthcare Informatics (MHI), Network and Communication Solutions (NCS). This strategic deployment enables NEXCOM to offer time-to-market, time-to-solution products and services without compromising on cost.

In addition, the service-to-market business model gives NEXCOM core competence in building a strong world-class service network by providing customized service, global logistics, local access, and real-time support. Operating six subsidiaries in China, Japan, Taiwan, and the United States, NEXCOM is able to better accommodate customers' requirements as well as closely work with global partners in different regions.

Partners can also be assured that NEXCOM's Taiwan-based Headquarters and subsidiary offices in China and the USA have obtained ISO 9001:2015 Certification.

Certificate

ISO 9001:2015

IAS	**IoT Automation Solutions**: Industrial Automation & I4.0 Execution, Intelligent Edge, Gateway & EWR, Industrial Robot Control, EtherCAT Motion Solutions, Wireless & Embedded Solutions for Industrial IoT
IDS	**Intelligent Video Surveillance**: IP Video Surveillance Cameras, Mobile Cameras, ANPR/LPR Network Cameras, Panoramic Cameras, NVR Server Platform
IPS	**Intelligent Platform @ Smart City**: Smart City, Smart Retail, Digital Signage, Interactive Kiosks, Hospitality, Healthcare, Gateway, Edge AI, and ODM Customization Services
MCS	**Mobile Computing Solutions**: Edge AI Telematics Computer, Vehicle Telematics Computer, Railway Computer, Vehicle Mount Computer, Vehicle Mount Display, In-Vehicle Networking, In-Vehicle HDMI Extender over IP, Fitness Console
MHI	**Medical and Healthcare Informatics**: Total Solutions with a Variety of Medical IT Systems
NCS	**Network and Communication Solutions**: Cybersecurity, OT Security, SD-WAN, SASE, Load Balancing, 5G uCPE, Edge AI

Corporate Vision

To become the industrial leader in providing AIoT digital transformation solutions, NEXCOM utilizes its industry leading technology, localized customer support and worldwide logistics services. This will be achieved by:

- Great team work
- Cooperation with trusted partners
- Growth through innovation

Corporate Mission

- An AIoT digital transformation supplier in vertical application markets
- A quality partner in engineering, manufacturing and services

Business Strategy

Aiming to better support the activities of all its partners, NEXCOM divides its sales force into six dedicated business units to target rapidly expanding vertical markets. This enables each business unit to focus on strategic channel accounts and repeat order business. Moreover, NEXCOM will provide customers with co-marketing strategies, technical support, ODM services, and project support, which are frequently required everywhere.

NEXCOM has already become a business group focused on innovating comprehensive solutions for Industry 4.0. We help our customers deliver vertical solutions optimized for 5G, AI, AIoT, and Industry 4.0 solutions.

Global Fulfillment Service

Product delivery and customer support are always more effective when delivered locally. NEXCOM localizes support and provides a global customer service network to handle all aspects of global business, from presales, order taking, and system assembly to logistics. For expeditious product delivery, NEXCOM has established four regional service centers: Taiwan (for Asia), USA (for North America and South America), and China. Therefore, NEXCOM customers benefit from quality assured product assembly and four service centers.

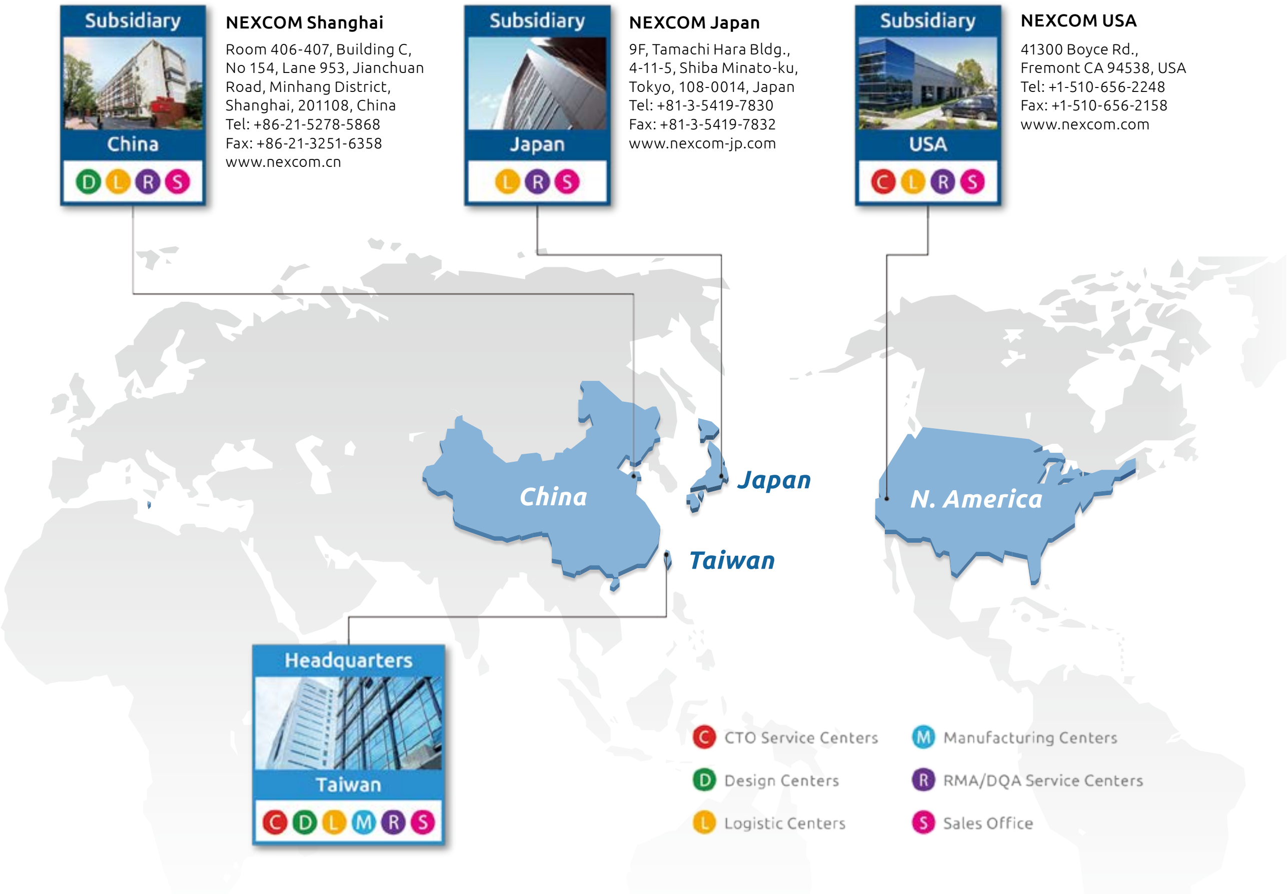
NEXCOM has invested heavily to establish operational infrastructures, including advanced equipment and facilities, not only at its global headquarters but also at subsidiary offices. Today, each of our service centers, with ISO 9001:2008 certification, has a purpose built assembly line, RMA/ DOA center and warehouse storage capability.

Quality Assurance

Under a strict Quality Assurance System, product design and reliability are controlled to support all critical solutions, and ensure Total Quality Assurance (TQA) implementation for all NEXCOM products and services. Additionally, NEXCOM's technical support team is aligned with ISO 27001 requirements, as they aim to provide timely feedback within 24 hours to resolve technical issues efficiently. This ensures that any potential information security incidents are addressed promptly, minimizing the impact and downtime for customers.

Green Policy

As a global citizen, NEXCOM places great importance on environmental issues. We are committed to ensuring that our products and services comply with environmental standards and regulations. NEXCOM actively responds to energy-saving and carbon reduction initiatives, prioritizes environmental protection in our operational activities, and holds certificate such as ISO 14064-1 greenhouse gas inventory and ISO 14001 environmental management system. We implement voluntary greenhouse gas inventory, reduce resource and energy consumption, and mitigate environmental risks. We also measure NEXCOM's sustainability and corporate responsibility as an Earth-friendly enterprise through ESG evaluation. NEXCOM will continue to collaborate with peers and suppliers to strive for purification standards, compatibility of technologies, and operational processes to help reduce the potential hazardous substances in our products and manufacturing processes.



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